

Host Memory Organization

HA1...	High Byte Address Compare
HA0...	Significant only if an HDLC mode with automatic address handling has been selected. In operating modes which provide high byte address recognition, the DSCC4 compares the high byte of a 2-byte address with the contents of two individually programmable addresses (RADR:RAH1, RADR:RAH2) and the fixed values FE_H and FC_H (broadcast address). Dependent on the result of this comparison, the following bit combinations are possible: 10...RAH1 has been recognized. 00...RAH2 has been recognized. 01...broadcast address has been recognized. If RAH1, RAH2 contain identical values, a match is indicated by '10'.
C/R...	Command/Response Significant only if 2-byte address mode has been selected. Value of the C/R bit (bit in high address byte) in the received frame. The interpretation depends on the setting of the CRI bit in the RADR register. Refer also to the description of RADR register.
LA...	Low Byte Address Compare Not significant in transparent and extended transparent operating mode. the below byte address of a 2-byte address field, or the single address byte of a 1-byte address field is compared with two addresses (RADR:RAL1, RADR:RAL2). 0...RAL2 has been recognized. 1...RAL1 has been recognized. According to the X.25 LAPB protocol, RAL1 is interpreted as the address of a COMMAND frame and RAL2 is interpreted as the address of a RESPONSE frame.

11.1.2.3 Receive Data Section Status Byte (ASYNC/BISYNC Modes)

In ASYNC/BISYNC protocol mode additionally to every data byte, an attached status byte can be stored (CCR2:RFDF='1').

The data character and status character format is determined as follows:

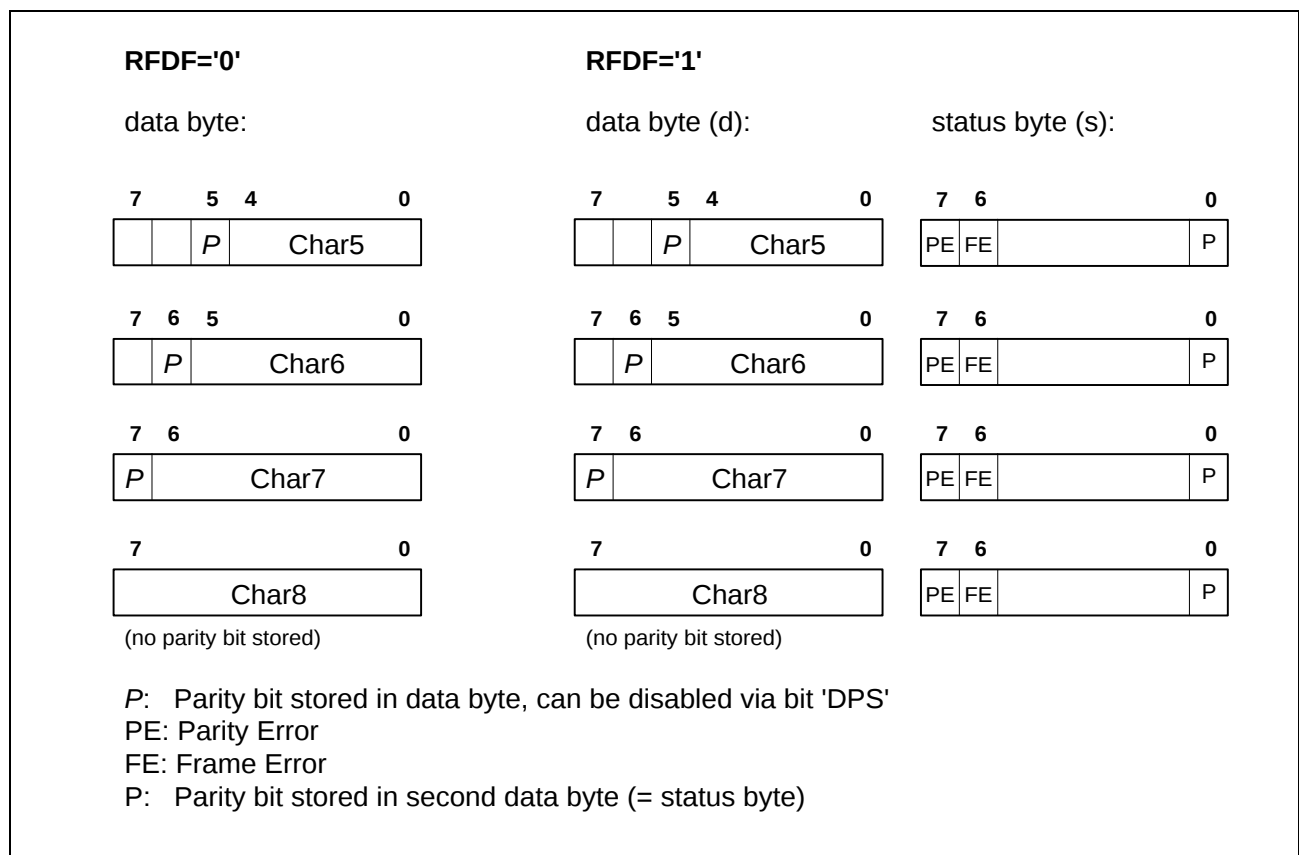


Figure 79 ASYNC/BISYNC Receive Status Character Format

Note: The 'Frame Error' (FE) status bit is only valid in ASYNC protocol mode.

11.2 Interrupt Queue Structure

11.2.1 Interrupt Queue Overview

The DSCC4 interrupt concept is based on 32-bit interrupt vectors generated by the different blocks. Interrupt vectors are stored in a central interrupt FIFO which is 16 DWORDs deep. The interrupt controller transfers available vectors in one of ten circular interrupt queues located in the shared memory. Each queue is dedicated to the interrupt source.

In addition new interrupt vectors are indicated in the global status register GSTAR on a per queue basis and selectively confirmed by writing '1' to the corresponding GSTAR bit positions. The PCI interrupt signal $\overline{\text{INTA}}$ is asserted with any new interrupt event and remains asserted until all events are confirmed.

(For more detailed information refer to chapter [“DMAC Interrupt Controller” on Page 81.](#))

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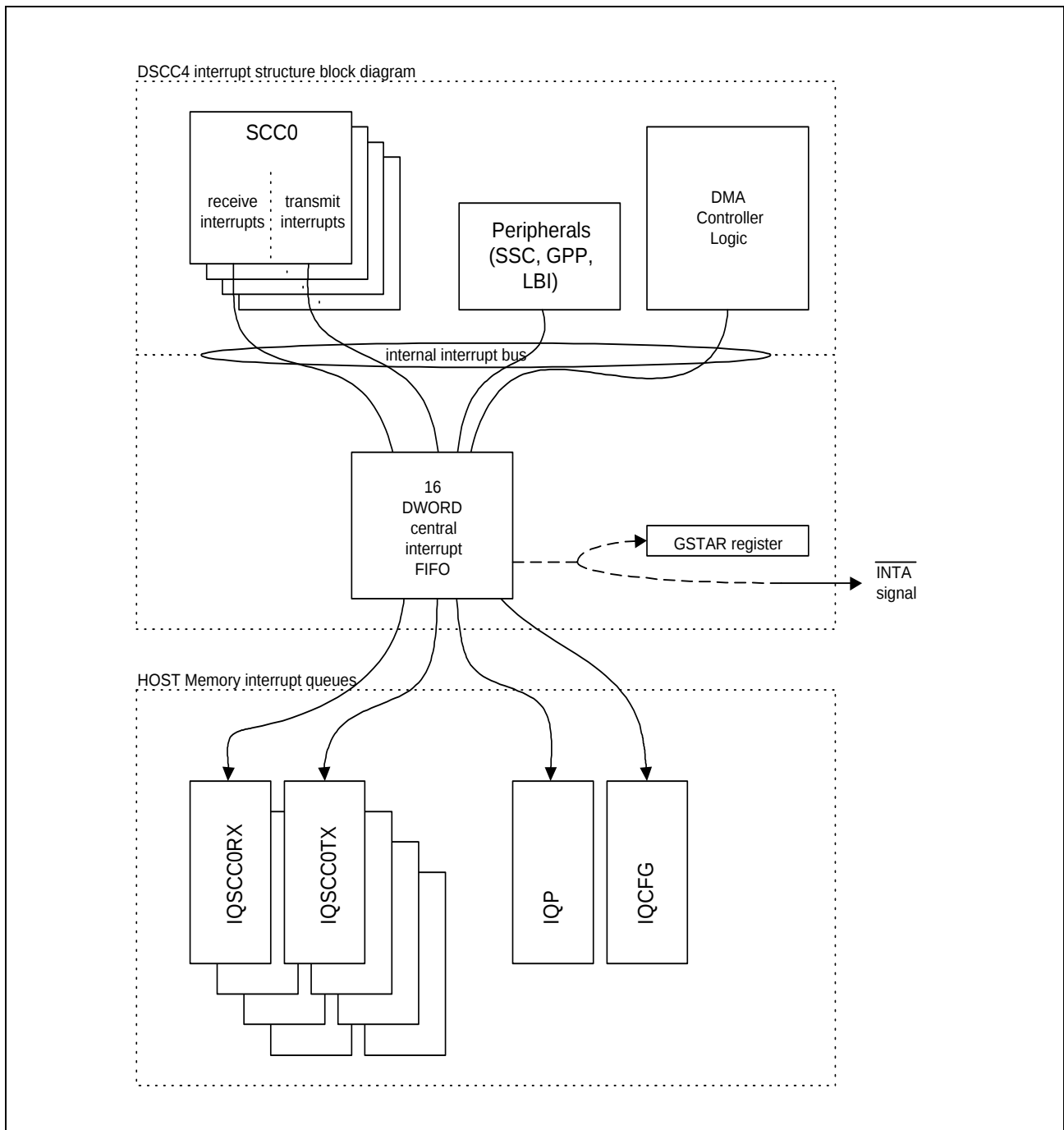


Figure 80 DSCC4 Logical Interrupt Structure

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11.2.2 Interrupt Vector Overview

Figure 81 provides an overview about all DSCC4 interrupt vectors. The different interrupt sources (types) are distinguished by the most significant 8 bit of the 32-bit interrupt vector. The dedicated host memory interrupt queues, the vectors are transferred to, are referenced in brackets under each interrupt vector name:

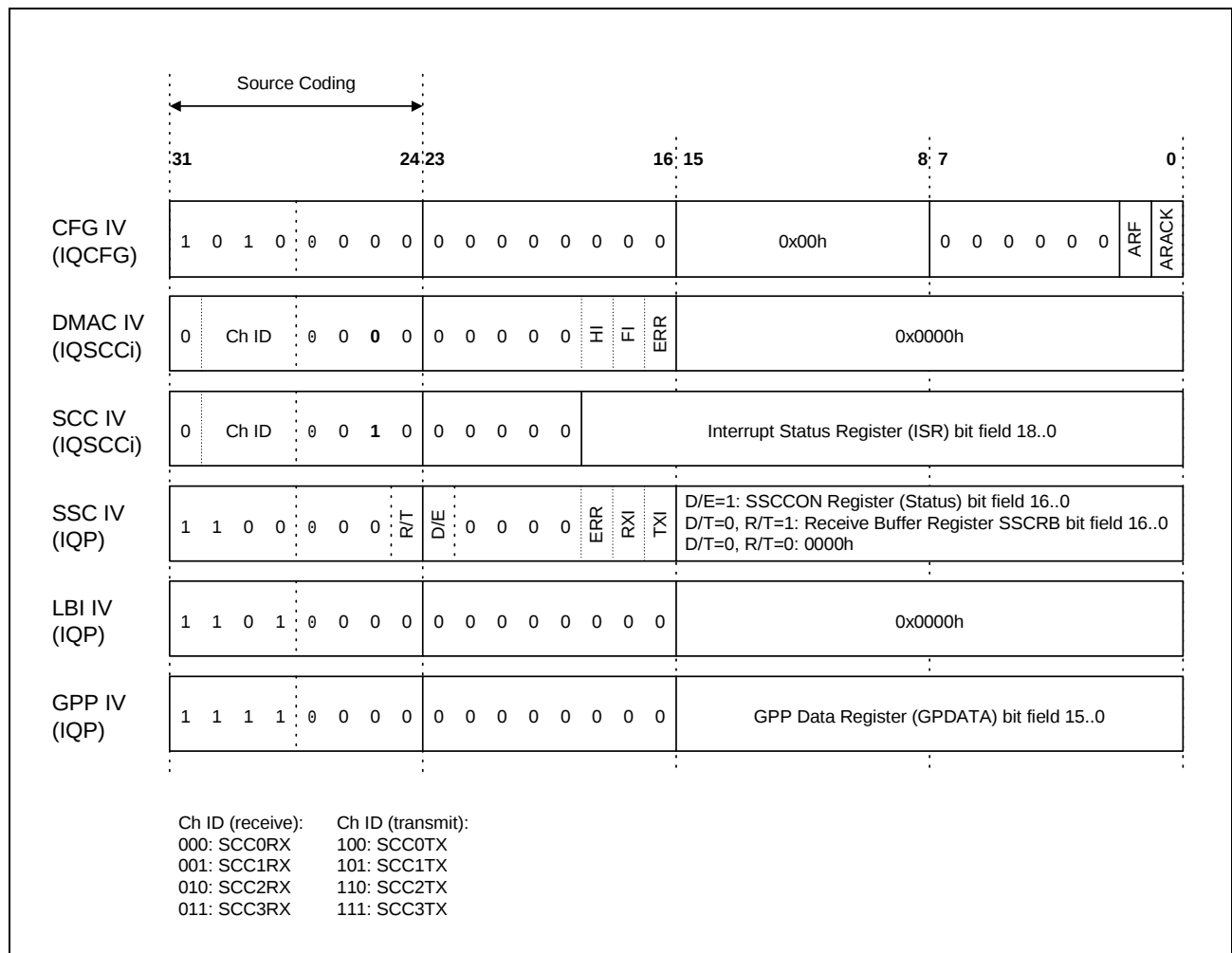


Figure 81 Interrupt Vector Overview

11.2.2.1 Configuration Interrupt Vector

Configuration interrupt vectors are transferred to Configuration Interrupt Queue 'IQCFG'.

Table 102 **CFGIV: Configuration Interrupt Vectori**

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
Source Id= 1010				0	0	0	0	0	0	0	0	0	0	0	0
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	0	0	0	0	0	0	0	ARF	ARACK

Source ID **1010₂** Configuration Interrupt Vector (IQCFG)

ARF **Action Request Failed Interrupt**

This bit indicates that an action request command was completed with an 'action request failed' condition:

ARF='0' No action request was performed or no 'action request failed' condition occurred completing an action request.

ARF='1' The last action request command was completed with an 'action request failed' condition.

ARACK **Action Request Acknowledge Interrupt**

This bit indicates that an action request command was completed successfully:

ARACK='0' No action request was performed or completed successfully.

ARACK='1' The last action request command was completed successfully.

11.2.2.2 DMA Controller Interrupt Vector

DMA controller interrupt vectors are transferred to the corresponding channel and direction specific interrupt queues IQSCCiRX and IQSCCiTX respectively.

Table 103 DMA Controller Interrupt Vectori

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
0	Source ID			0	0	0	0	0	0	0	0	0	HI	FI	ERR
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Source ID	000₂	Receive Channel 0 Interrupt Vector (IQSCC0RX)
	001₂	Receive Channel 1 Interrupt Vector (IQSCC1RX)
	010₂	Receive Channel 2 Interrupt Vector (IQSCC2RX)
	011₂	Receive Channel 3 Interrupt Vector (IQSCC3RX)
	100₂	Transmit Channel 0 Interrupt Vector (IQSCC0TX)
	101₂	Transmit Channel 1 Interrupt Vector (IQSCC1TX)
	110₂	Transmit Channel 2 Interrupt Vector (IQSCC2TX)
	111₂	Transmit Channel 3 Interrupt Vector (IQSCC3TX)

HI	Host Initiated interrupt	(Rx/Tx Channel)
This bit indicates that an Host Initiated (HI) interrupt occurred, i.e. the corresponding DMA controller channel detects the 'HI' bit set to '1' in the receive or transmit descriptor before branching to the next descriptor.		
HI='0'	No Host Initiated (HI) interrupt is indicated by this vector.	
HI='1'	An Host Initiated (HI) interrupt is indicated by this vector.	

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FI **Frame Indication interrupt** (Rx/Tx Channel)

This bit indicates that an Frame Indication (FI) interrupt occurred.

Receive direction:

FI='1' indicates, that a frame has been received completely or was stopped by a DMAC receiver reset command or a hold condition set in a receive descriptor. It is set when the DSCC4 branches from the last descriptor belonging to the current frame (or block) (FE='1') to the first descriptor of a new frame. It is also set when the descriptor in which the frame/block is finished contained a hold condition.

Transmit direction:

Issued if the 'FE' bit is detected in the transmit descriptor. It is set when the DSCC4 branches to the next transmit descriptor, belonging to a new frame or when 'HOLD' bit is set in conjunction with 'FE' bit. Only 'ERR' indication without 'FI' is set, if a transmit descriptor contains a 'HOLD' (hold condition) but no 'FE' bit.

FI='0' No Frame Indication (FI) interrupt is indicated by this vector.

FI='1' An Frame Indication (FI) interrupt is indicated by this vector.

ERR **ERROR Indication interrupt** (Rx/Tx Channel)

This bit indicates that an Error interrupt occurred.

Receive direction:

Issued if the current frame/block could not be transferred to the shared memory completely, because of a hold condition in a receive descriptor not providing enough bytes for the frame/block or the frame/block was aborted by a DMAC receiver reset command.

Transmit direction:

Issued if a transmit descriptor contains a hold condition but FE='0' or if the last descriptor had NO=0 and FE='0'.

ERR='0' No Error (ERR) interrupt is indicated by this vector.

ERR='1' An Error (ERR) interrupt is indicated by this vector.

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11.2.2.3 SCC Interrupt Vector

Serial Channel (SCC) related interrupt vectors are transferred to the corresponding channel and direction specific interrupt queues IQSCCiRX and IQSCCiTX respectively.

Note: Interrupt vectors generated by the SCCs might contain interrupt indications for both, receive AND transmit direction. But in receive interrupt queues only the receive interrupt indications need to be served and in transmit interrupt queues only transmit interrupt indications need to be served by the software.

Table 104 SCC Interrupt Vector

Mode	31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
H	0	Source ID				0	0	1	0	0	0	0	0	ALLS	0	XDU
A	0	Source ID				0	0	1	0	0	0	0	0	ALLS	0	XOFF
B	0	Source ID				0	0	1	0	0	0	0	0	ALLS	0	XDU

Mode	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
H	TIN	CSC	XMR	XPR	0	0	0	0	RDO	RFS	RSC	PCE	PLLA	CDSC	RFO	FLEX
A	TIN	CSC	XON	XPR	0	0	BRK	BRKT	TCD	TIME	PERR	FERR	PLLA	CDSC	RFO	0
B	TIN	CSC	XMR	XPR	0	0	0	0	TCD	0	PERR	SCD	PLLA	CDSC	RFO	0

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Source ID	000₂	Receive Channel 0 Interrupt Vector (IQSCC0RX)
	001₂	Receive Channel 1 Interrupt Vector (IQSCC1RX)
	010₂	Receive Channel 2 Interrupt Vector (IQSCC2RX)
	011₂	Receive Channel 3 Interrupt Vector (IQSCC3RX)
	100₂	Transmit Channel 0 Interrupt Vector (IQSCC0TX)
	101₂	Transmit Channel 1 Interrupt Vector (IQSCC1TX)
	110₂	Transmit Channel 2 Interrupt Vector (IQSCC2TX)
	111₂	Transmit Channel 3 Interrupt Vector (IQSCC3TX)

Bit field 18..0 of the SCC interrupt vector is a copy of the SCC Interrupt Status Register ISR. The meaning of the bit field depends on the selected protocol mode (HDLC (H), ASYNC (A), BISYNC (B)).

(For detailed information on Interrupt Status Register ISR refer to [Table 87 "ISR: Interrupt Status Register" on Page 342.](#))

11.2.2.4 SSC Interrupt Vector

SSC interrupt vectors are transferred to the peripheral interrupt queue IQP.

Table 105 SSC Interrupt Vector

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
1	1	0	0	0	0	0	R/T	D/E	0	0	0	0	ERR	RX	TX
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
ISW(15:0)															

(Source ID) 1100₂ **SSC Interrupt Vector (IQP)**
bit field
31..28

R/T Receive/Transmit Indicator

This bit indicates whether the SSC vector is generated for transmit or receive interrupt events:

R/T='0' SSC transmit interrupt vector.

R/T='1' SSC receive interrupt vector.

D/E Data/Error Indicator

This bit indicates whether the SSC vector is generated for data (transmit/receive) or error interrupt events:

D/E='0' SSC error interrupt vector.

D/E='1' SSC data interrupt vector.

ERR Error interrupt

This bit indicates that an error interrupt occurred:

ERR='0' No error interrupt is indicated by this vector.

ERR='1' An error interrupt is indicated by this vector.
 Bit field 15..0 contains the corresponding bit field 15..0 of register SSCCON (operation mode).

RX Receive interrupt

This bit indicates that a receive interrupt occurred:

- RX='0' No receive interrupt is indicated by this vector.
- RX='1' A receive interrupt is indicated by this vector.
Bit field 15..0 contains the corresponding bit field 15..0 of register SSCRb (receive buffer containing the received data bits).

TX Transmit interrupt

This bit indicates that a transmit interrupt occurred:

- TX='0' No transmit interrupt is indicated by this vector.
- TX='1' A transmit interrupt is indicated by this vector.
Bit field 15..0 contains a constant zero value. This interrupt means, that the transmit buffer can be reloaded with new transmit data (register SSCTB).

ISW(15:0) Interrupt Status Word

The contents of this bit field depends on the SSC interrupt type:

- | Type: | Meaning: |
|---------------------------------------|--|
| error int.
(D/E='0') | ISW(15:0) = SSCCON(15:0)
(Register SSCCON in operational mode.) |
| receive int.
(D/E='1',
R/T='1') | ISW(15:0) = SSCRb(15:0)
(Register SSCRb.) |
| transm. int.
(D/E='1',
R/T='0') | ISW(15:0) = 0000 _H |

11.2.2.5 LBI Interrupt Vector

LBI interrupt vectors are transferred to the peripheral interrupt queue IQP.

Table 106 LBI Interrupt Vector

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

(Source ID) 1101₂ LBI Interrupt Vector (IQP)
bit field
31..28

This interrupt vector (with no additional bit information) is generated, if a state transition inactive to active is detected at LBI interrupt input signal LINTI1.

The polarity (high or low active) of input signal LINTI1 is determined by bit 'LINTIC' in register LCONF.

11.2.2.6 GPP Interrupt Vector

GPP interrupt vectors are transferred to the peripheral interrupt queue IQP.

Table 107 GPP Interrupt Vectori

31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16
1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
GPSTA(15:0)															

(Source ID) 1111₂ GPP Interrupt Vector (IQP)
bit field
31..28

GPSTA (15:0) **General Purpose Port Status Information**

This bit field 15..0 reflects the changes (high-to-low or low-to-high transition) detected on the GPP pins. The actual state (input level) of these pins can be determined by reading the general purpose data register GPDATA.

Whenever a transition on at least one general purpose pin is detected, a GPP interrupt vector is generated (if unmasked).

12 Test Configuration

12.1 JTAG Boundary Scan Interface

In the DSCC4 a Test Access Port (TAP) controller is implemented. The essential part of the TAP is a finite state machine (16 states) controlling the different operational modes of the boundary scan. Both, TAP controller and boundary scan, meet the requirements given by the JTAG standard: IEEE 1149.1. **Figure 82** gives an overview about the TAP controller.

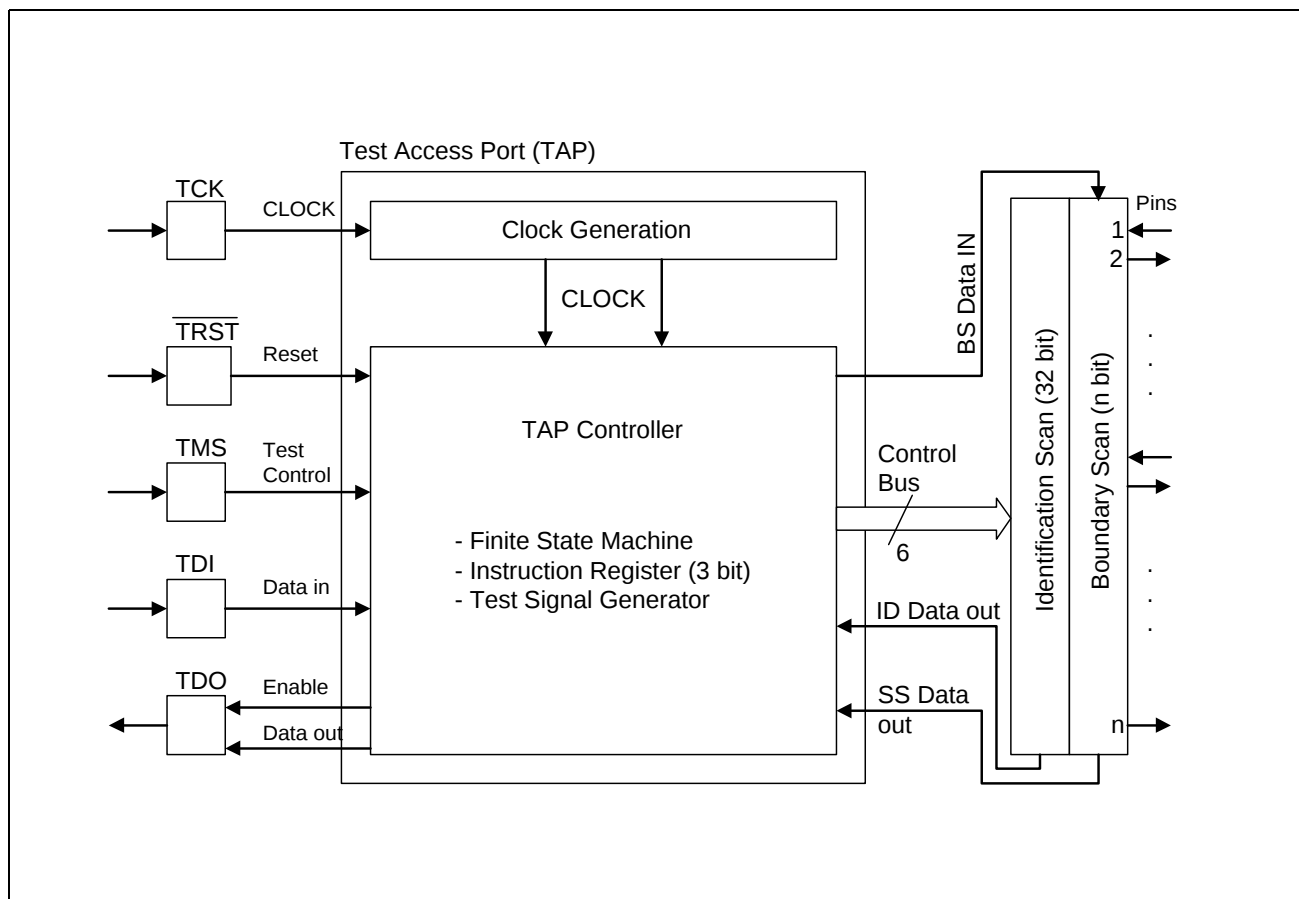


Figure 82 **Block Diagram of Test Access Port and Boundary Scan Unit**

If no boundary scan operation is planned $\overline{\text{TRST}}$ has to be connected with V_{SS} . TMS and TDI do not need to be connected since pull-up transistors ensure high input levels in this case. Nevertheless it would be a good practice to put the unused inputs to defined levels. In this case, if the JTAG is not used:

TMS = TCK = '1' is recommended.

Test handling (boundary scan operation) is performed via the pins TCK (Test Clock), TMS (Test Mode Select), TDI (Test Data Input) and TDO (Test Data Output) when the TAP controller is not in its reset state, i.e. $\overline{\text{TRST}}$ is connected to V_{DD} or it remains unconnected due to its internal pull-up. Test data at TDI are loaded with a 4-MHz clock

Test Configuration

signal connected to TCK. '1' or '0' on TMS causes a transition from one controller state to another; constant '1' on TMS leads to normal operation of the chip.

Table 108 Boundary Scan Sequence of the DSCC4

TDI ->

Seq. No.	Pin	I/O	Number of Boundary Scan Cells	Constant Value In, Out, Enable
1	$\overline{\text{INTA}}$	I/O	3	001
2	AD0	I/O	3	100
3	AD1	I/O	3	000
4	AD2	I/O	3	000
5	AD3	I/O	3	001
6	AD4	I/O	3	101
7	AD5	I/O	3	100
8	AD6	I/O	3	000
9	$\text{C}/\overline{\text{BE0}}$	I/O	3	100
10	AD7	I/O	3	000
11	AD8	I/O	3	110
12	AD9	I/O	3	000
13	AD10	I/O	3	000
14	AD11	I/O	3	000
15	AD12	I/O	3	000
16	AD13	I/O	3	000
17	AD14	I/O	3	000
18	AD15	I/O	3	000
19	$\text{C}/\overline{\text{BE1}}$	I/O	3	000
20	PAR	I/O	3	000
21	$\overline{\text{SERR}}$	I/O	3	000
22	$\overline{\text{PERR}}$	I/O	3	000
23	$\overline{\text{STOP}}$	I/O	3	000
24	$\overline{\text{DEVSEL}}$	I/O	3	000
25	$\overline{\text{TRDY}}$	I/O	3	000
26	$\overline{\text{IRDY}}$	I/O	3	000

Test Configuration

Seq. No.	Pin	I/O	Number of Boundary Scan Cells	Constant Value In, Out, Enable
27	FRAME	I/O	3	000
28	C/BE2	I/O	3	000
29	AD16	I/O	3	000
30	AD17	I/O	3	000
31	AD18	I/O	3	000
32	AD19	I/O	3	000
33	AD20	I/O	3	000
34	AD21	I/O	3	000
35	AD22	I/O	3	000
36	AD23	I/O	3	000
37	IDSEL	I/O	3	000
38	C/BE3	I/O	3	000
39	AD24	I/O	3	000
40	AD25	I/O	3	000
41	AD26	I/O	3	000
42	AD27	I/O	3	000
43	AD28	I/O	3	000
44	AD29	I/O	3	000
45	AD30	I/O	3	000
46	AD31	I/O	3	000
47	REQ	I/O	3	000
48	GNT	I/O	3	000
49	CLK	I	1	0
50	RST	I/O	3	000
51	W/R	I/O	3	000
52	DEMUX	I/O	3	000
53	RTS3	I/O	3	000
54	CD3	I/O	3	000
55	CTS3	I/O	3	000
56	TXD3	I/O	3	000

Test Configuration

Seq. No.	Pin	I/O	Number of Boundary Scan Cells	Constant Value In, Out, Enable
57	RXD3	I/O	3	000
58	TXCLK3	I/O	3	000
59	RXCLK3	I/O	3	000
60	$\overline{\text{RTS2}}$	I/O	3	000
61	CD2	I/O	3	000
62	$\overline{\text{CTS2}}$	I/O	3	000
63	TXD2	I/O	3	000
64	RXD2	I/O	3	000
65	TXCLK2	I/O	3	000
66	RXCLK2	I/O	3	000
67	LALE	I/O	3	000
68	LINTO	I/O	3	000
69	LINTI2	I/O	3	000
70	LINTI1	I/O	3	000
71	$\overline{\text{LRDY}}$	I/O	3	000
72	$\overline{\text{LBHE}}$	I/O	3	000
73	$\overline{\text{LWR}}$	I/O	3	000
74	$\overline{\text{LRD}}$	I/O	3	000
75	$\overline{\text{LCSi}}$	I/O	3	000
76	$\overline{\text{LCSO}}$	I/O	3	000
77	$\overline{\text{LBREQ}}$	I/O	3	000
78	$\overline{\text{LHLDA}}$	I/O	3	000
79	$\overline{\text{LHOLD}}$	I/O	3	000
80	LD0	I/O	3	000
81	LD1	I/O	3	000
82	LD2	I/O	3	000
83	LD3	I/O	3	000
84	LD4	I/O	3	000
85	LD5	I/O	3	000
86	LD6	I/O	3	000

Test Configuration

Seq. No.	Pin	I/O	Number of Boundary Scan Cells	Constant Value In, Out, Enable
87	LD7	I/O	3	000
88	LD8	I/O	3	000
89	LD9	I/O	3	000
90	LD10	I/O	3	000
91	LD11	I/O	3	000
92	LD12	I/O	3	000
93	LD13	I/O	3	000
94	LD14	I/O	3	000
95	LD15	I/O	3	000
96	LA0	I/O	3	000
97	LA1	I/O	3	000
98	LA2	I/O	3	000
99	LA3	I/O	3	000
100	LA4	I/O	3	000
101	LA5	I/O	3	000
102	LA6	I/O	3	000
103	LA7	I/O	3	000
104	LA8	I/O	3	000
105	LA9	I/O	3	000
106	LA10	I/O	3	000
107	LA11 $\bar{1}$	I/O	3	000
108	LA12 $\bar{2}$	I/O	3	000
109	LA13 $\bar{3}$	I/O	3	000
110	LA14 $\bar{4}$	I/O	3	000
111	LA15 $\bar{5}$	I/O	3	000
112	RTS1	I/O	3	000
113	CD1	I/O	3	000
114	CTS1	I/O	3	000
115	TXD1	I/O	3	000
116	RXD1	I/O	3	000

Test Configuration

Seq. No.	Pin	I/O	Number of Boundary Scan Cells	Constant Value In, Out, Enable
117	TXCLK1	I/O	3	000
118	RXCLK1	I/O	3	000
119	TEST	I	1	0
120	RTS0	I/O	3	000
121	CD0	I/O	3	000
122	CTS0	I/O	3	000
123	TXD0	I/O	3	000
124	RXD0	I/O	3	000
125	TXCLK0	I/O	3	000
126	RXCLK0	I/O	3	000

-> TDO

An input pin (I) uses one boundary scan cell (data in), an output pin (O) uses two cells (data out, enable) and an I/O-pin (I/O) uses three cells (data in, data out, enable). Note that some functional output and input pins of the DSCC4 are tested as I/O pins in boundary scan, hence using three cells. The boundary scan unit of the DSCC4 contains a total of $n = 374$ scan cells.

The right column of [Table 108](#) gives the initialization values of the cells.

The desired test mode is selected by serially loading a 3-bit instruction code into the instruction register via TDI (LSB first); see [Table 109](#).

Table 109 Boundary Scan Test Modes

Instruction (Bit 2 ... 0)	Test Mode
000	EXTEST (external testing)
001	INTEST (internal testing)
010	SAMPLE/PRELOAD (snap-shot testing)
011	IDCODE (reading ID code)
111	BYPASS (bypass operation)
others	handled like BYPASS

EXTEST is used to examine the interconnection of the devices on the board. In this test mode at first all input pins **capture** the current level on the corresponding external interconnection line, whereas all output pins are held at constant values ('0' or '1',

Test Configuration

according to [Table 108](#)). Then the contents of the boundary scan is **shifted** to TDO. At the same time the next scan vector is loaded from TDI. Subsequently all output pins are **updated** according to the new boundary scan contents and all input pins again capture the current external level afterwards, and so on.

INTEST supports internal testing of the chip, i.e. the output pins **capture** the current level on the corresponding internal line whereas all input pins are held on constant values ('0' or '1', according to [Table 108](#)). The resulting boundary scan vector is **shifted** to TDO. The next test vector is serially loaded via TDI. Then all input pins are **updated** for the following test cycle.

Note: In capture IR-state the code '001' is automatically loaded into the instruction register, i.e. if INTEST is wanted the shift IR-state does not need to be passed.

SAMPLE/PRELOAD is a test mode which provides a snap-shot of pin levels during normal operation.

IDCODE: A 32-bit identification register is serially read out via TDO. It contains the version number (4 bits), the device code (16 bits) and the manufacturer code (11 bits). The LSB is fixed to '1'.

TDI ->	0011	0000 0000 0011 0110	0000 1000 001	1	-> TDO
--------	------	---------------------	---------------	---	--------

Note: Since in test logic reset state the code '011' is automatically loaded into the instruction register, the ID code can easily be read out in shift DR state which is reached by TMS = 0, 1, 0, 0.

BYPASS: A bit entering TDI is shifted to TDO after one TCK clock cycle.

13 Electrical Characteristics

13.1 Important Electrical Requirements

$$V_{DD3} = 3.3 \text{ V} \pm 0.3 \text{ V}$$

$$V_{DD3 \text{ max}} = 3.6 \text{ V}$$

$$V_{DD5} = 5.0 \text{ V} \pm 0.25 \text{ V}$$

$$V_{DD5 \text{ max}} = 5.25 \text{ V}$$

During all DSCC4 power-up and power-down situations the difference $|V_{DD5} - V_{DD3}|$ may not exceed 3.6V. The absolute maximums of V_{DD5} and V_{DD3} should never be exceeded.

Figure 83 shows that both V_{DD3} and V_{DD5} can take on any time sequence, not exceeding a voltage difference of 3.6V, for up to 50 milliseconds at power-up and power-down. Within 50 milliseconds of power-up the voltages must be within their respective absolute voltage limits. At power-down, within 50 milliseconds of either voltage going outside its operational range, the voltage difference should not exceed 3.6V and both voltages must be returned below 0.1V:

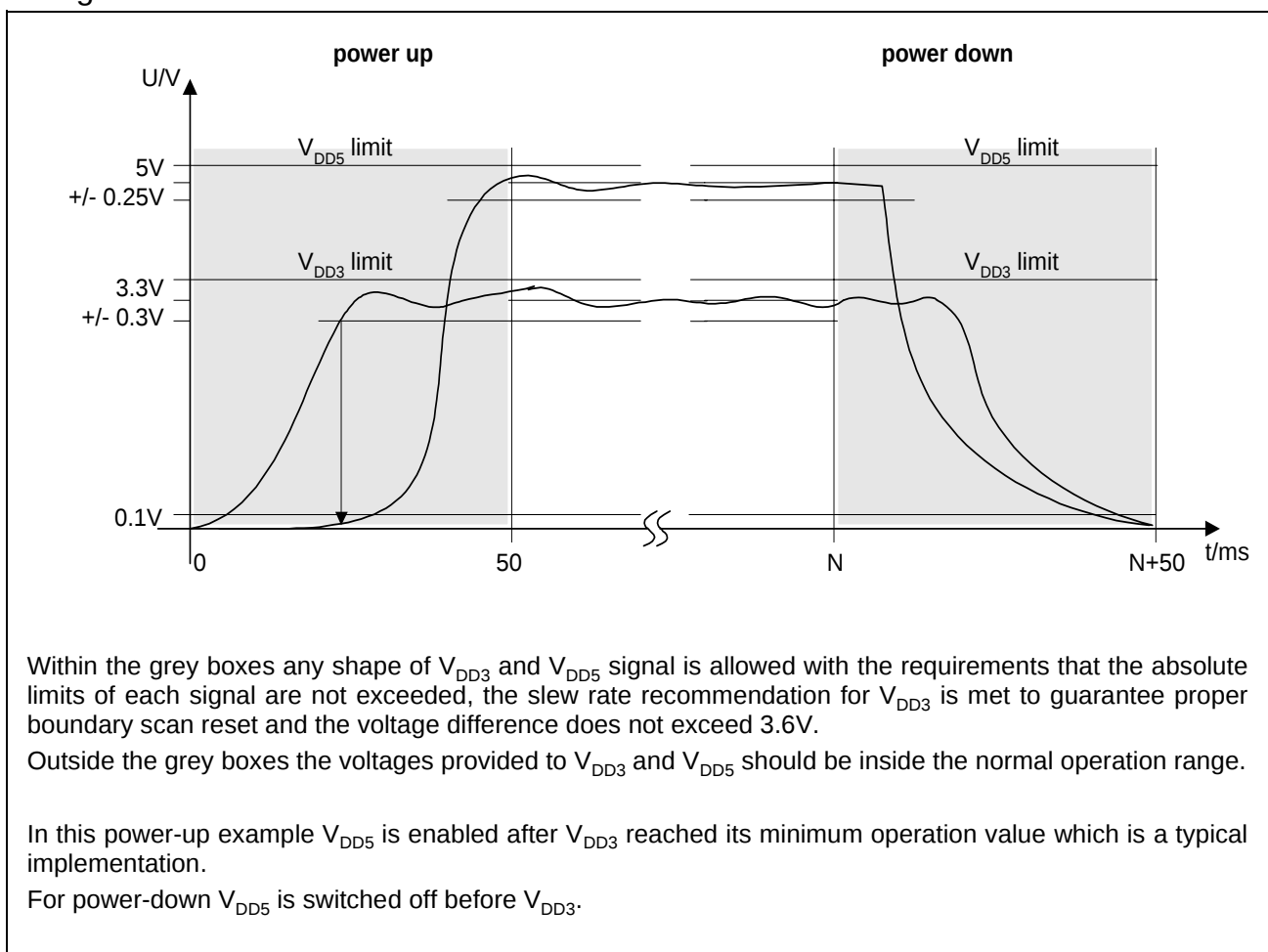


Figure 83 Power-up and Power-down scenarios

Similar criteria also apply to power down in case of power failure situations:

Electrical Characteristics

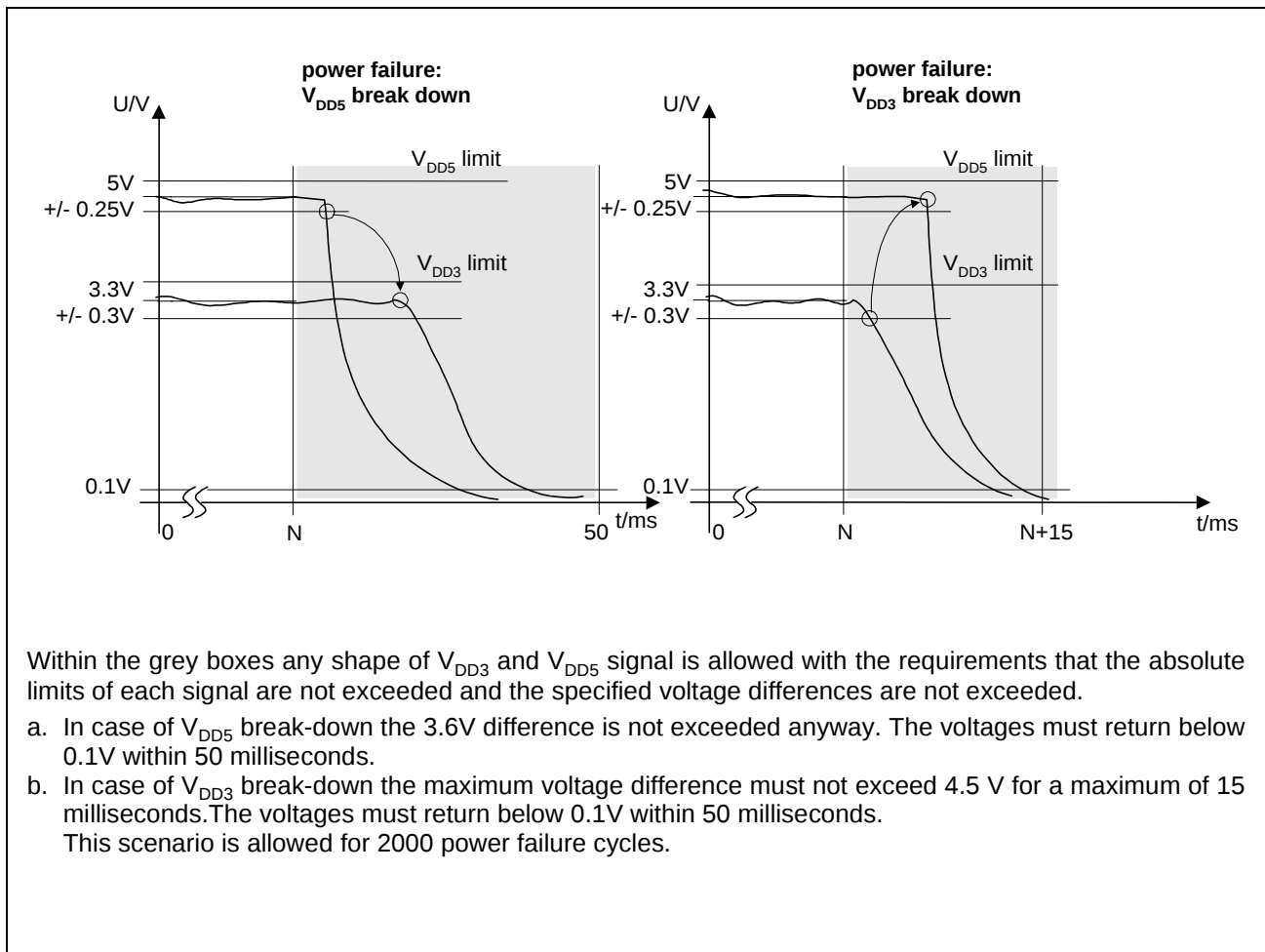


Figure 84 Power-Failure scenarios

Additional recommendations:

The pin TEST has to be tied to V_{SS} (refer to pin description table).

Electrical Characteristics

13.2 Absolute Maximum Ratings

Table 110 Absolute Maximum Ratings

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Ambient temperature under bias	T_A	0	70	°C
Junction temperature under bias	T_J		125	°C
Storage temperature	T_{stg}	– 65	125	°C
Voltage at any pin with respect to ground	V_S	– 0.4	$V_{DD5} + 0.4$	V

Note: Stresses above those listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

13.3 Thermal Package Characteristics

Table 111 Thermal Package Characteristics

Parameter		Symbol	Value	Unit
Thermal Package Resistance Junction to Ambient				
Airflow:	Ambient Temperature:			
without airflow	T _A =-40°C	θ _{JA(0,-40)}	42.3	°C/K
without airflow	T _A =+25°C	θ _{JA(0,25)}	37.2	°C/K
airflow 1 m/s	T _A =+25°C	θ _{JA(1,25)}	34.9	°C/K
airflow 2 m/s	T _A =+25°C	θ _{JA(2,25)}	33.3	°C/K
airflow 3 m/s	T _A =+25°C	θ _{JA(3,25)}	32.2	°C/K

13.4 DC Characteristics

a) Non-PCI Interface Pins and Power Supply Pins

Table 112 DC Characteristics (Non-PCI Interface Pins and Power Supply Pins)

$T_A = 0 \text{ to } +70 \text{ }^\circ\text{C}$; $V_{DD5} = 5 \text{ V} \pm 5 \%$, $V_{DD3} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $V_{SS} = 0 \text{ V}$

Parameter		Symbol	Limit Values		Unit	Test Condition
			min.	max.		
L-input voltage		V_{IL}	-0.4	0.8	V	
H-input voltage		V_{IH}	2.0	$V_{DD5} + 0.4$	V	
L-output voltage		V_{QL}		0.45	V	$I_{QL} = 7 \text{ mA}$ (pin TXD) $I_{QL} = 2 \text{ mA}$ (all others / non-PCI)
H-output voltage		V_{QH}	2.4	V_{DD3}	V	$I_{QH} = -400 \text{ } \mu\text{A}$
Power supply current V_{DD3}	operational	I_{CC3}		< 300	mA	inputs at V_{SS}/V_{DD} , no output loads
	power down (no clocks)	I_{CC3}		< 2	mA	
Power supply current V_{DD5}		I_{CC5}		< 2	mA	
Power dissipation		P		< 1090	mW	
typical values	operational current	$I_{CC3 \text{ typ.}}$		< 250	mA	$V_{DD3} = 3.3\text{V}$, inputs at V_{SS}/V_{DD} , no output loads
	power dissipation	$P_{\text{typ.}}$		< 830	mW	
Input leakage current Output leakage current		I_{LI} I_{LQ}		1	μA	$0 \text{ V} < V_{IN} < V_{DD}$ to 0 V $0 \text{ V} < V_{OUT} < V_{DD}$ to 0 V (pins with internal pull-ups excluded)

Note: 1. The listed characteristics are ensured over the operating range of the integrated circuit. Typical characteristics specify mean values expected over the production spread. If not otherwise specified, typical characteristics apply at $T_A = 25 \text{ }^\circ\text{C}$ and the given supply voltage.

Note: 2. The electrical characteristics described in [Section 13.2](#) also apply here!

Electrical Characteristics

b) PCI Pins

According to the PCI specification V2.1 from June 1, 1995
(Chapter 4.2.1: Electrical DC Specifications for 5 V signaling)

Table 113 DC Characteristics PCI Interface Pins

$T_A = 0 \text{ to } +70 \text{ }^\circ\text{C}$; $V_{DD5} = 5 \text{ V} \pm 5 \%$, $V_{DD3} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $V_{SS} = 0 \text{ V}$

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
L-input voltage	V_{IL}	-0.5	0.8	V	
H-input voltage	V_{IH}	2.0	$V_{DD5} + 0.5$	V	
L-output voltage	V_{QL}		0.45	V	$I_{QL} = 3 \text{ mA}$
H-output voltage	V_{QH}	2.4	V_{DD3}	V	$I_{QH} = -2 \text{ mA}$

13.5 Capacitances

a) Non-PCI Interface Pins

Table 114 Capacitances (Non-PCI Interface Pins)

$T_A = 25 \text{ }^\circ\text{C}$; $V_{DD5} = 5 \text{ V} \pm 5\%$, $V_{DD3} = 3.3 \text{ V} \pm 0.3 \text{ V}$, $V_{SS} = 0 \text{ V}$

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input capacitance	C_{IN}	1	5	pF	
Output capacitance	C_{OUT}	5	10	pF	
I/O-capacitance	C_{IO}	6	15	pF	

b) PCI Pins

According to the PCI specification V2.1 from June 1, 1995 (Chapter 4: Electrical Specification for 5 V signalling)

13.6 AC Characteristics

a) Non-PCI Interface Pins

$T_A = 0 \text{ to } +70 \text{ }^\circ\text{C}$; $V_{DD5} = 5 \text{ V} \pm 5\%$; $V_{DD3} = 3.3 \text{ V} \pm 0.3 \text{ V}$

Inputs are driven to 2.4 V for a logical “1” and to 0.4 V for a logical “0”. Timing measurements are made at 2.0 V for a logical “1” and at 0.8 V for a logical “0”.

The AC testing input/output waveforms are shown below.

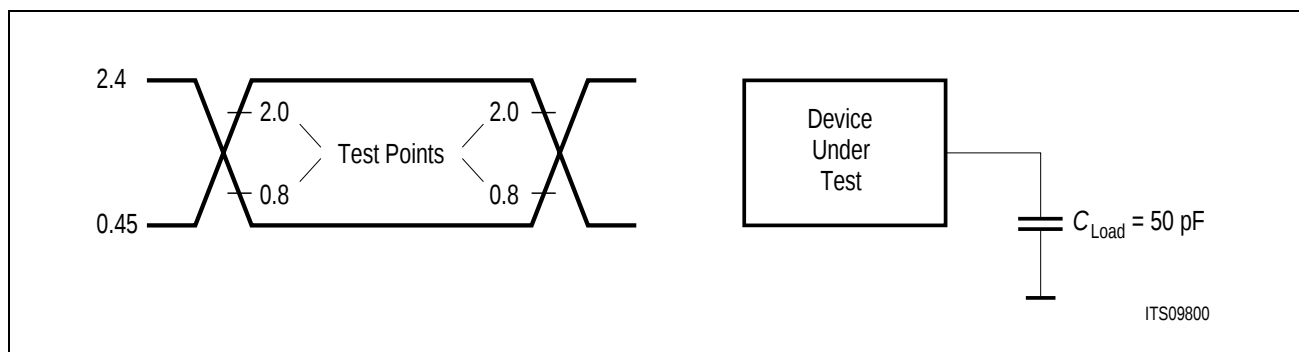


Figure 85 Input/Output Waveform for AC Tests

b) PCI Pins

According to the PCI specification V2.1 from June 1, 1995 (Chapter 4: Electrical Specification for 5 V signalling)

13.6.1 PCI Bus Interface Timing

The AC testing input/output waveforms are shown in [Figure 86](#) and [Figure 87](#) below.

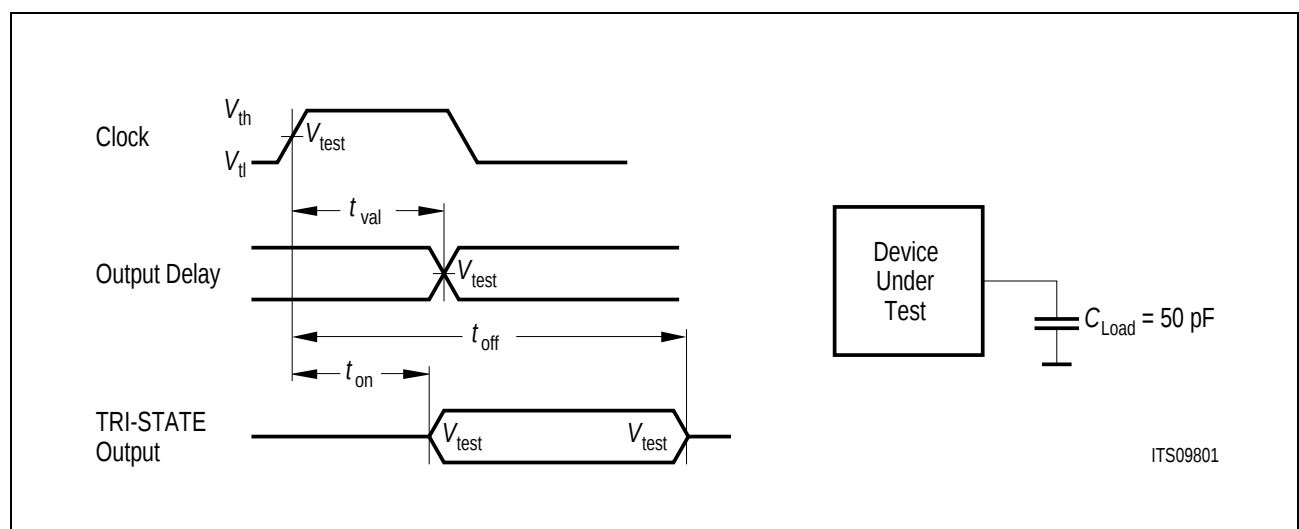


Figure 86 PCI Output Timing Measurement Waveforms

Electrical Characteristics

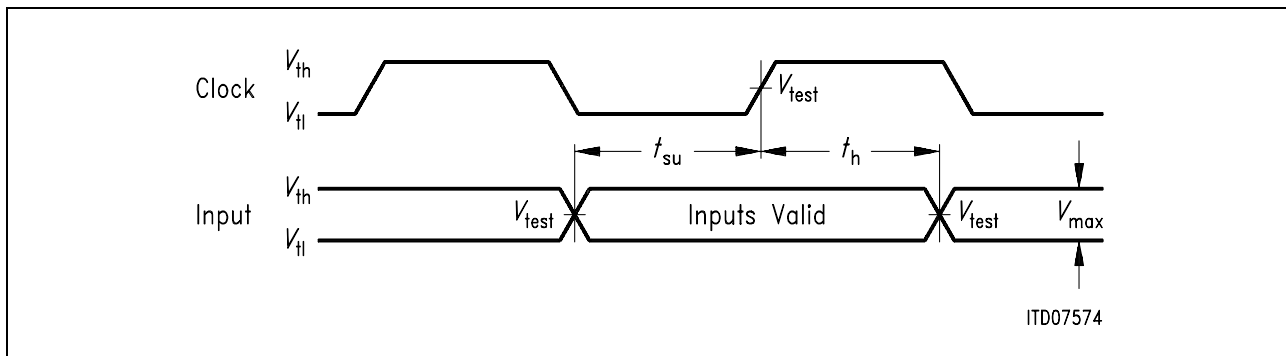


Figure 87 PCI Input Timing Measurement Waveforms

Table 115 PCI Input and Output Measurement Conditions

Symbol	Value	Unit
V_{th}	2.4	V
V_{tl}	0.4	V
V_{test}	1.5	V
V_{max}	2.0	V

The timings below show the basic read and write transaction between an initiator (Master) and a target (Slave) device. The DSCC4 is able to work both as master and slave.

As a master the DSCC4 reads/writes data from/to host memory using DMA and burst. The slave mode is used by an CPU to access the DSCC4 PCI Configuration Space, the on-chip registers and to access peripherals connected to the DSCC4 Local Bus Interface (LBI).

13.6.1.1 PCI Read Transaction

The transaction starts with an address phase which occurs during the first cycle when $\overline{FRAME}$ is activated (clock 2 in [Figure 88](#)). During this phase the bus master (initiator) outputs a valid address on AD(31:0) and a valid bus command on $\overline{C/BE}(3:0)$. The first clock of the first data phase is clock 3. During the data phase $\overline{C/BE}$ indicate which byte lanes on AD(31:0) are involved in the current data phase.

The first data phase on a read transaction requires a turn-around cycle. In [Figure 88](#) the address is valid on clock 2 and then the master stops driving AD. The target drives the AD lines following the turnaround when $\overline{DEVSEL}$ is asserted. ($\overline{TRDY}$ cannot be driven until $\overline{DEVSEL}$ is asserted.) The earliest the target can provide valid data is clock 4. Once enabled, the AD output buffers of the target stay enabled through the end of the transaction.

Electrical Characteristics

A data phase may consist of a data transfer and wait cycles. A data phase completes when data is transferred, which occurs when both $\overline{\text{IRDY}}$ and $\overline{\text{TRDY}}$ are asserted. When either is deasserted a wait cycle is inserted. In the example below, data is successfully transferred on clocks 4, 6 and 8, and wait cycles are inserted on clocks 3, 5 and 7. The first data phase completes in the minimum time for a read transaction. The second data phase is extended on clock 5 because $\overline{\text{TRDY}}$ is deasserted. The last data phase is extended because $\overline{\text{IRDY}}$ is deasserted on clock 7.

The Master knows at clock 7 that the next data phase is the last. However, the master is not ready to complete the last transfer, so $\overline{\text{IRDY}}$ is deasserted on clock 7, and $\overline{\text{FRAME}}$ stays asserted. Only when $\overline{\text{IRDY}}$ is asserted can $\overline{\text{FRAME}}$ be deasserted, which occurs on clock 8.

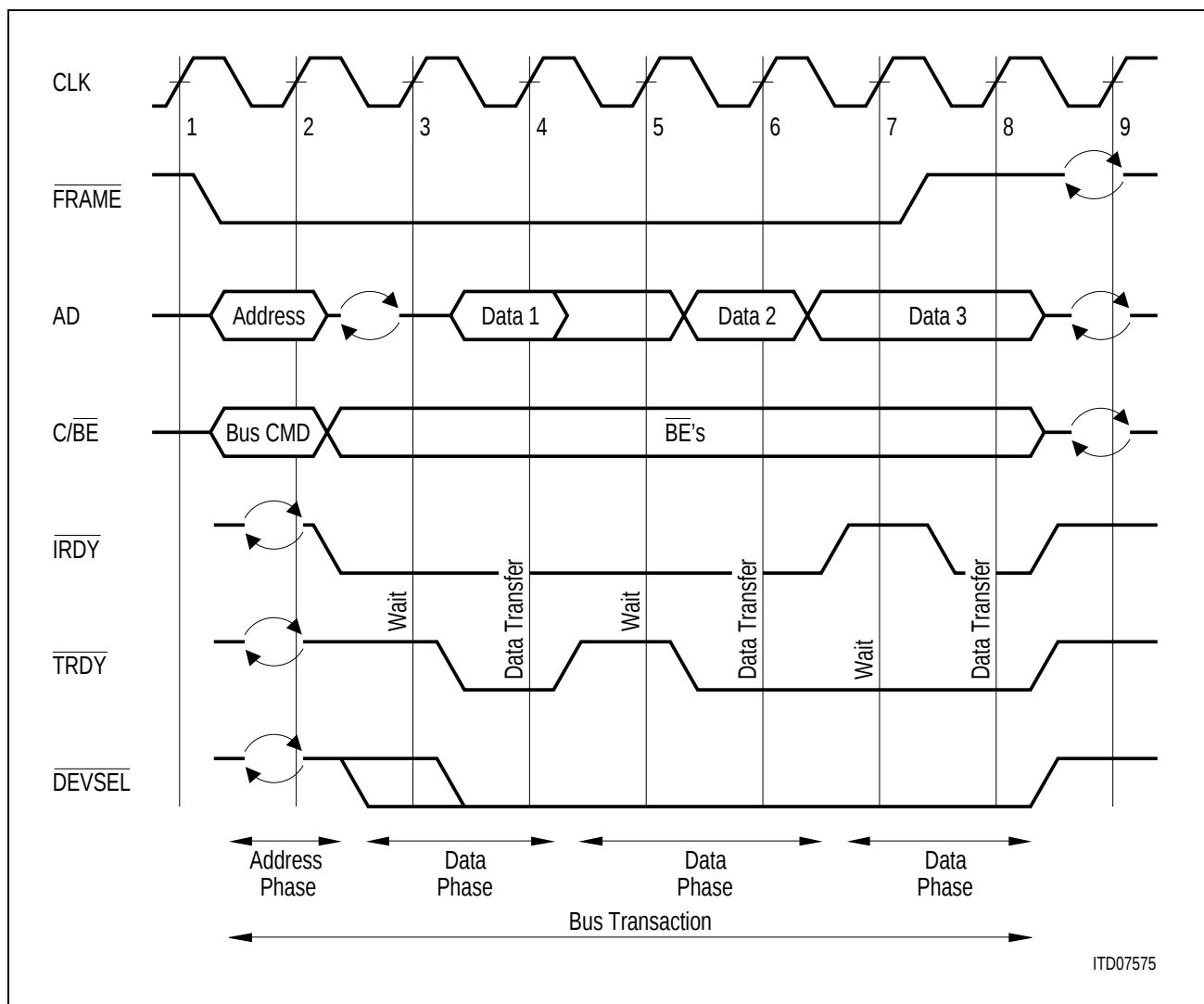


Figure 88 PCI Read Transaction

13.6.1.2 PCI Write Transaction

The transaction starts when $\overline{\text{FRAME}}$ is activated (clock 2 in [Figure 89](#)). A write transaction is similar to a read transaction except no turnaround cycle is required following the address phase. In the example, the first and second data phases complete with zero wait cycles. The third data phase has three wait cycles inserted by the target. Both initiator and target insert a wait cycle on clock 5. In the case where the initiator inserts a wait cycle (clock 5), the data is held on the bus, but the byte enables are withdrawn. The last data phase is characterized by $\overline{\text{IRDY}}$ being asserted while the $\overline{\text{FRAME}}$ signal is deasserted. This data phase is completed when $\overline{\text{TRDY}}$ goes active (clock 8).

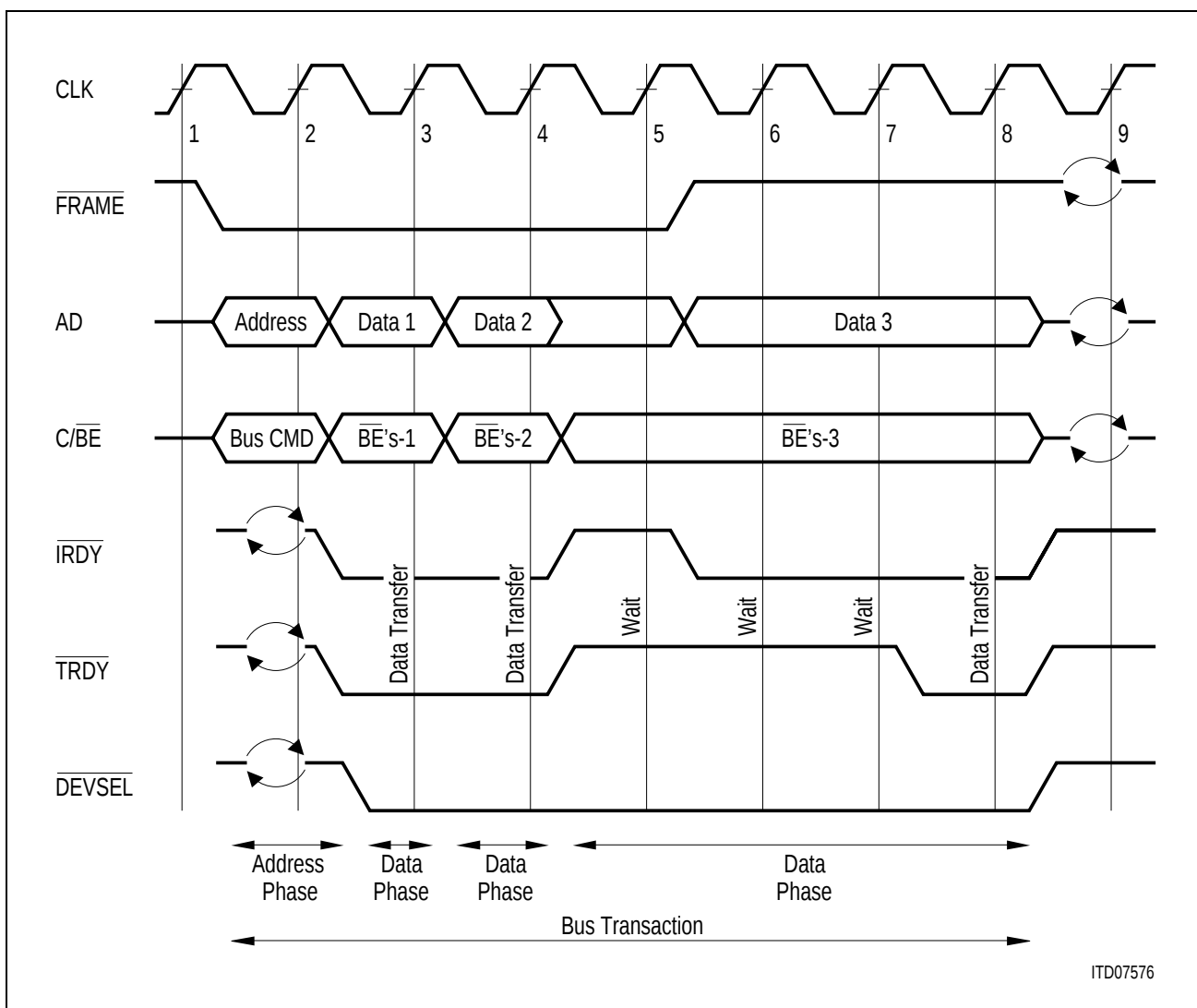


Figure 89 PCI Write Transaction

13.6.1.3 PCI Timing Characteristics

When the DSCC4 operates as a PCI Master (initiator) and it either reads or writes a burst – as controlled by the on-chip DMA controller – it does not deactivate $\overline{\text{IRDY}}$ between consecutive data. In other words, no wait states are inserted by the DSCC4 as a transaction initiator. The numbers of wait states, inserted by the DSCC4 as initiator are listed in [Table 116](#).

Table 116 Number of Wait States Inserted by the DSCC4 as Initiator

Transaction	Number of Wait States	
	1st Data Cycle	2nd and Subsequent Data Cycles
Memory read burst	0	0
Memory write burst	0	0
Fast Back-to-back burst; 1st transaction	0	0
Fast Back-to-back burst; 2nd and subsequent transactions	1	0

When the DSCC4 operates as a PCI Slave (target), it inserts wait cycles by deactivating $\overline{\text{TRDY}}$. The numbers of wait states, typically inserted by the DSCC4 are listed in [Table 116](#):

Table 117 Number of Wait States Inserted by the DSCC4 as Slave

Transaction	Number of Wait States
Configuration read	2
Configuration write	0
Register read	3
Register write	0
LBI read	3
LBI write	0

The number of wait states inserted by the DSCC4 as target is not critical because accesses to/via the DSCC4 are usually kept to a minimum in a system.

Electrical Characteristics

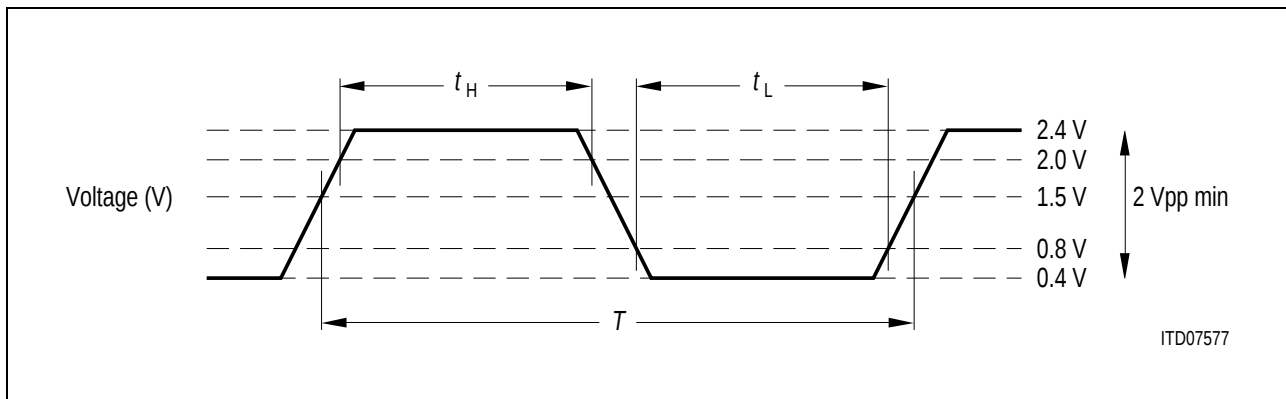


Figure 90 PCI Clock Specification

Table 118 PCI Clock Characteristics

Parameter	Symbol	Limit Values			Unit
		min.	typ.	max.	
CLK cycle time	T	30			ns
CLK high time	t_H	11			ns
CLK low time	t_L	11			ns
CLK slew rate (see note)		1		4	V/ns

Note: Rise and fall times are specified in terms of the edge rate measured in V/ns. This slew rate must be met across the minimum peak-to-peak portion of the clock waveform as shown in [Figure 90](#).

Electrical Characteristics

Table 119 PCI Interface Signal Characteristics

Parameter	Limit Values			Unit	Remarks
	min.	typ.	max.		
CLK to signal valid delay bussed signals	(2)		11	ns	Notes 1, 2
CLK to signal valid delay point-to-point	(2)		12	ns	Notes 1, 2
Float to active delay	2		(3)	ns	
Active to float delay			20	ns	
Input setup time to CLK bussed signals	7			ns	Note 2
Input setup time to CLK point-to-point	10			ns	Note 2
Input hold time from CLK	0			ns	

Note 1 Minimum times are measured with 0 pF equivalent load; maximum times are measured with 50 pF equivalent load.

Note 2 $\overline{REQ}$ and $\overline{GNT}$ are point-to-point signals. All other signals are bussed
 $\overline{GNT}$ setup (min) time: 10ns

13.6.2 De-multiplexed Bus Interface

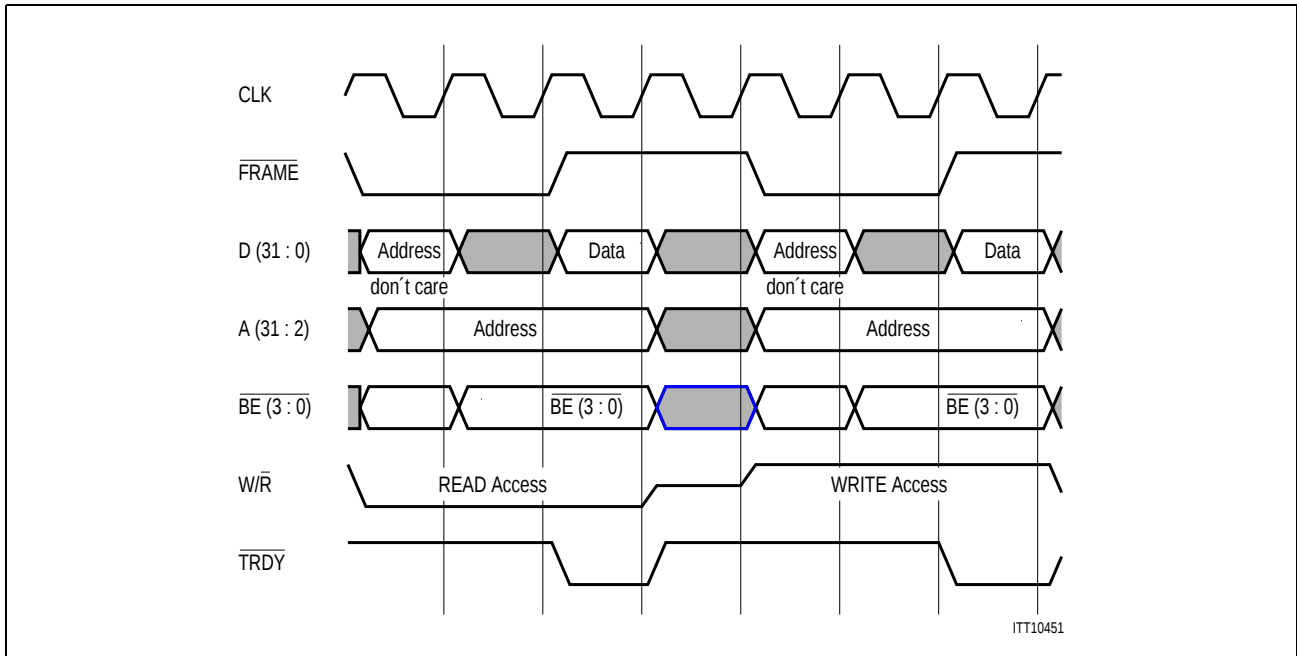


Figure 91 Master Single READ Transaction followed by a Master Single WRITE Transaction in De-multiplexed Bus Configuration

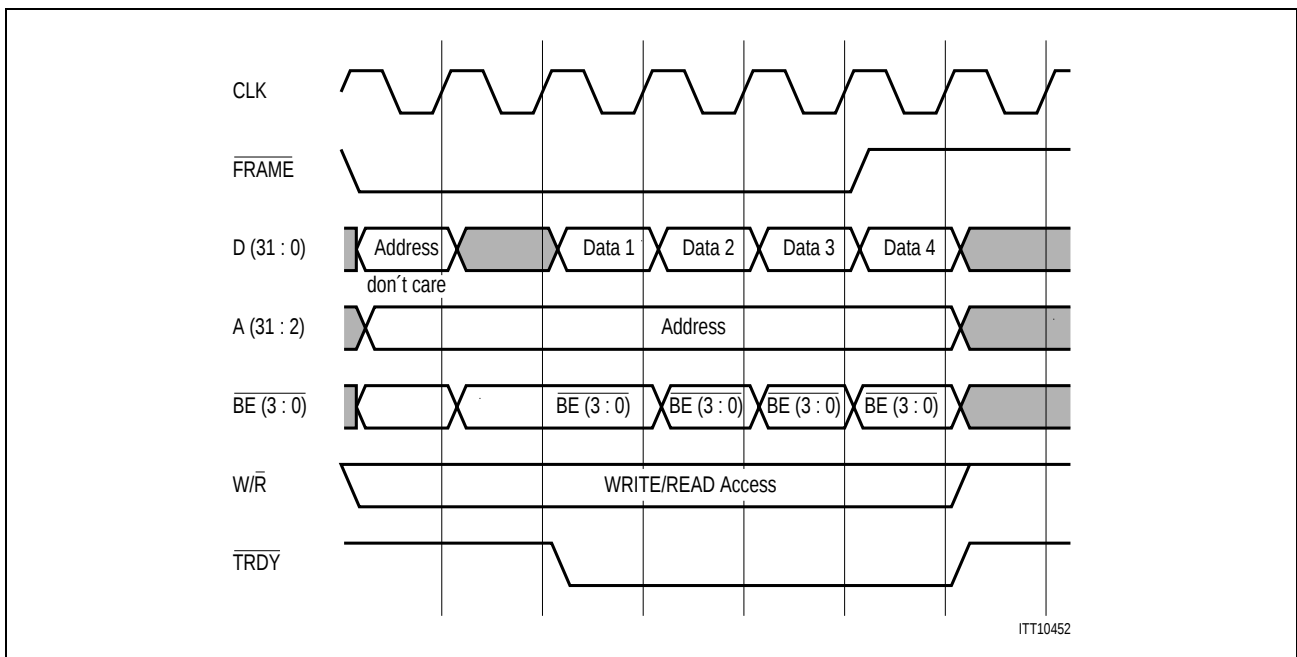


Figure 92 Master Burst WRITE/READ Access in De-multiplexed Bus Configuration

The timing provided in [Table 118](#) and [Table 119](#) can also be applied to the de-multiplexed bus interface.

Electrical Characteristics

Table 120 Additional De-multiplexed Interface Signal Characteristics

Parameter	Limit Values			Unit	Remarks
	min.	typ.	max.		
CLK to address bus signal valid delay			12	ns	
CLK to W/ $\bar{R}$ signal valid delay			12	ns	
Address bus Input setup time to CLK	8			ns	
Address bus Input hold time to CLK	0			ns	
W/ $\bar{R}$ signal Input setup time to CLK	8			ns	
W/ $\bar{R}$ signal Input hold time to CLK	0			ns	

Note: The PCI parity signal PAR is not generated in de-multiplexed mode. It is driven active low by the DSCC4.

13.6.3 Local Bus Interface Timing

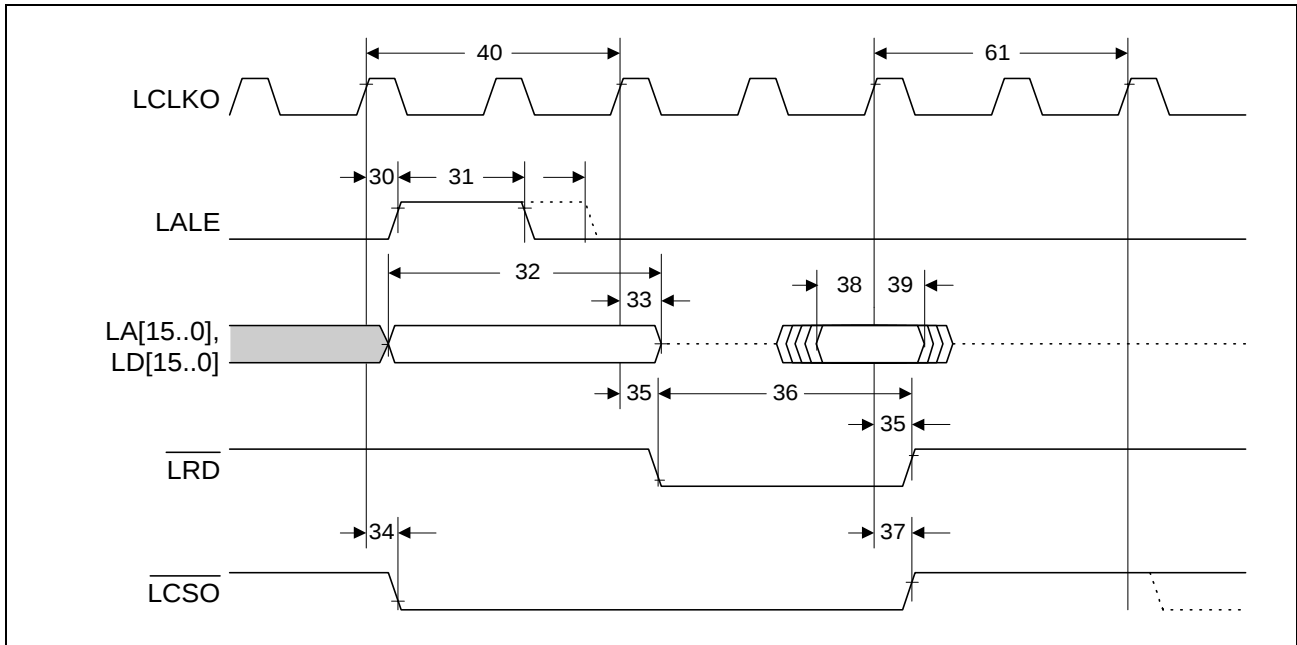


Figure 93 Synchronous LBI Read Cycle Timing Multiplexed Bus

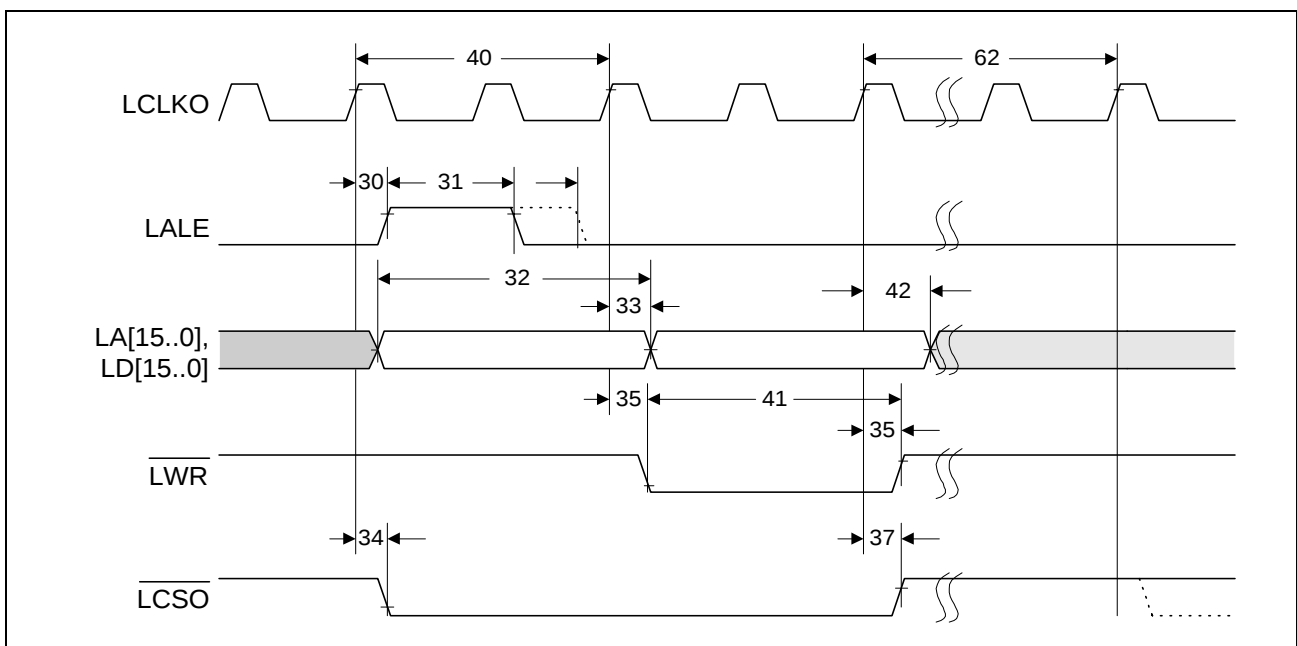


Figure 94 Synchronous LBI Write Cycle Timing Multiplexed Bus

Electrical Characteristics

Table 121 LBI Timing (synchronous, multiplexed bus)

No.	Parameter	Limit Values		Unit
		min.	max.	
30	LALE to LCLKO delay	5	20	ns
31	LALE pulse width	$1 T_{LBICKL}$ $(1.25 T_{LBICKL})^{1)}$		(ns)
32	Address phase width	$2 T_{LBICKL}$		(ns)
33	LA, $\overline{LBHE}$ hold to LCLKO delay	5	20	ns
34	$\overline{LCSO}$ active to LCLKO delay	5	20	ns
35	$\overline{LRD}$, $\overline{LWR}$ active/inactive to LCLKO delay	5	20	ns
36	$\overline{LRD}$ pulse width	$2T_{LBICKL} + MCTC + T_{LRDY}$		(ns)
37	$\overline{LCSO}$ inactive to LCLKO delay	5	20	ns
38	LD to LCLKO setup time	0		ns
39	LD to LCLKO hold time	25		ns
40	$\overline{LRD}$, $\overline{LWR}$ active to cycle start delay	$2 T_{LBICKL}$		(ns)
61	cycle end to next cycle start delay	$2 T_{LBICKL}$		(ns)
41	$\overline{LWR}$ pulse width	$2T_{LBICKL} + MCTC + T_{LRDY}$		(ns)
42	LD to LCLKO hold delay	$1 T_{PCICKL} + 5$	$1 T_{PCICKL} + 20$	ns
	LD to $\overline{LWR}$ inactive delay	$1 T_{PCICKL}$		(ns)
	LD tristate delay to LCLKO		$1 T_{PCICKL} + 20$	ns
62	cycle end to next cycle start delay	$5 T_{LBICKL}$		(ns)

¹⁾ If extended LALE timing is selected via bit 'EALE' in register LCONF

Note: T_{LBICKL} is the LBI clock time period which depends on the LBI clock division factor.
MCTC is the number of master clock wait states (in LBI clock cycles) selected in register LCONF.

T_{LRDY} is the number of additional wait states (in LBI clock cycles) introduced by $\overline{LRDY}$ control signal if enabled via bit 'RDEN' in register LCONF.

T_{PCICKL} is the PCI clock time period.

Electrical Characteristics

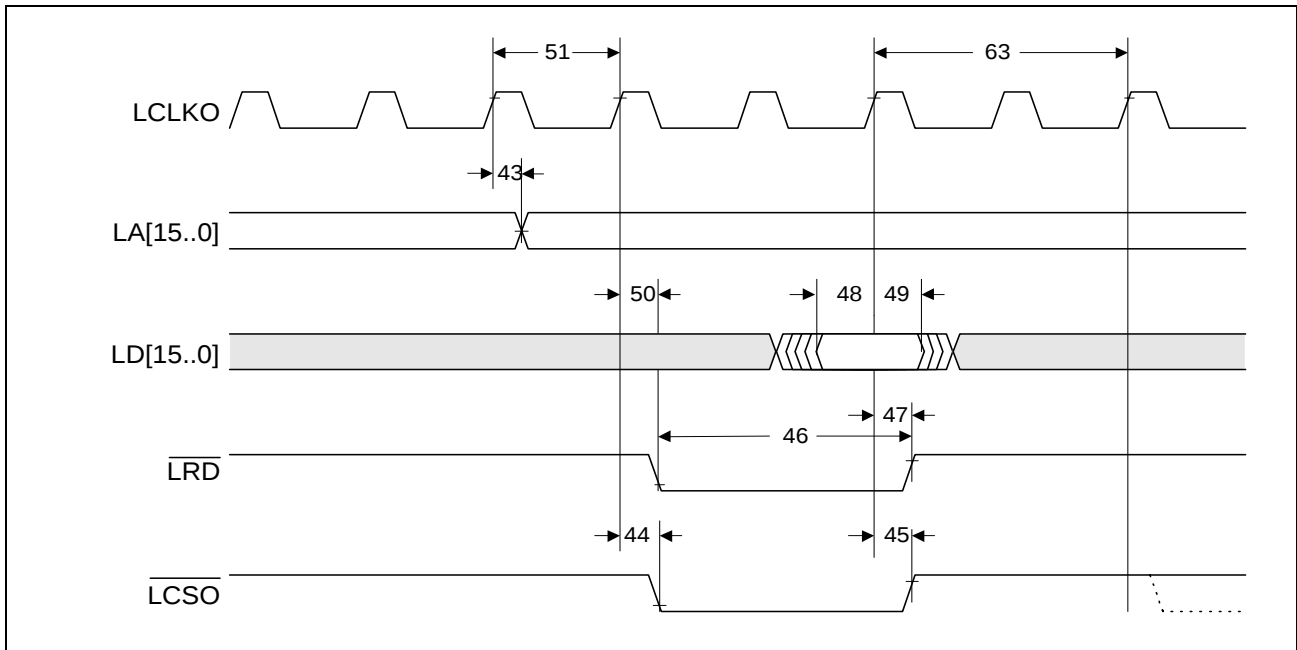


Figure 95 Synchronous LBI Read Cycle Timing De-multiplexed Bus

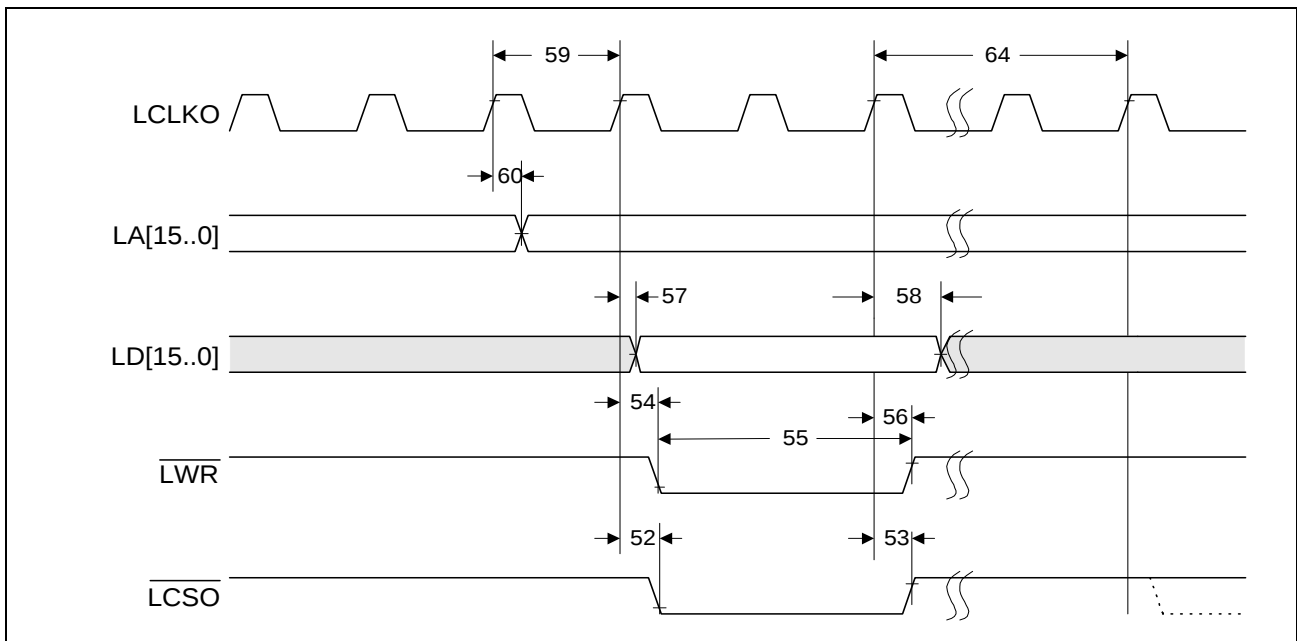


Figure 96 Synchronous LBI Write Cycle Timing De-multiplexed Bus

Electrical Characteristics

Table 122 LBI Timing (synchronous, de-multiplexed bus)

No.	Parameter	Limit Values		Unit
		min.	max.	
43	LA to LCLKO delay	5	20	ns
44	$\overline{\text{LCSO}}$ active to LCLKO delay	5	20	ns
45	$\overline{\text{LCSO}}$ inactive to LCLKO delay	5	20	ns
46	$\overline{\text{LRD}}$ pulse width	$2T_{\text{LBICKL}} + \text{MCTC} + T_{\text{LRDY}}$		(ns)
47	$\overline{\text{LRD}}$, $\overline{\text{LWR}}$ inactive to LCLKO delay	5	20	ns
48	LD to LCLKO setup time		0	ns
49	LD to LCLKO hold time		25	ns
50	$\overline{\text{LRD}}$, $\overline{\text{LWR}}$ active to LCLKO delay	5	20	ns
51	$\overline{\text{LRD}}$ active to cycle start delay	$1 T_{\text{LBICKL}}$		(ns)
63	cycle end to next cycle start delay	$2 T_{\text{LBICKL}}$		ns
52	$\overline{\text{LCSO}}$ active to LCLKO delay	5	20	ns
53	$\overline{\text{LCSO}}$ inactive to LCLKO delay	5	20	ns
54	$\overline{\text{LWR}}$ active to LCLKO delay	5	20	ns
55	$\overline{\text{LWR}}$ pulse width	$2T_{\text{LBICKL}} + \text{MCTC} + T_{\text{LRDY}}$		(ns)
56	$\overline{\text{LRD}}$, $\overline{\text{LWR}}$ inactive to LCLKO delay	5	20	ns
57	LD valid after LCLKO delay	5	20	ns
58	LD hold after LCLKO delay	$1 T_{\text{PCICKL}} + 5$	$1 T_{\text{PCICKL}} + 20$	ns
	LD to $\overline{\text{LWR}}$ inactive delay	$1 T_{\text{PCICKL}}$		(ns)
	LD tristate delay after LCLKO		$1 T_{\text{PCICKL}} + 20$	ns
59	$\overline{\text{LWR}}$ active to cycle start delay	$1 T_{\text{LBICKL}}$		(ns)
60	LA to LCLKO delay	5	20	ns
64	cycle end to next cycle start delay	$5 T_{\text{LBICKL}}$		(ns)

Note: T_{LBICKL} is the LBI clock time period which depends on the LBI clock division factor.
MCTC is the number of master clock wait states (in LBI clock cycles) selected in register LCONF.

T_{LRDY} is the number of additional wait states (in LBI clock cycles) introduced by $\overline{\text{LRDY}}$ control signal if enabled via bit 'RDEN' in register LCONF.

T_{PCICKL} is the PCI clock time period.

Electrical Characteristics

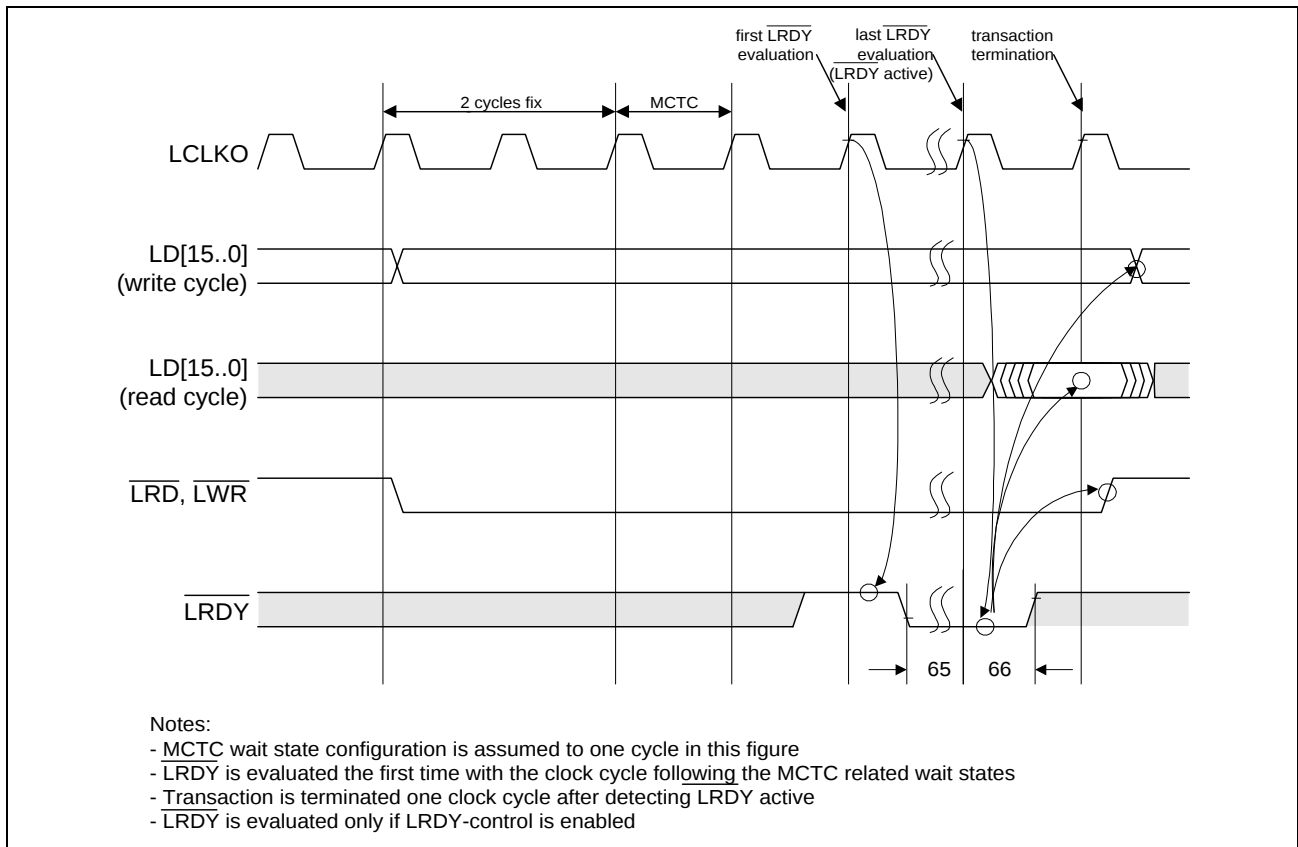


Figure 97 $\overline{\text{LRDY}}$ Timing

Table 123 LBI $\overline{\text{LRDY}}$ Timing

No.	Parameter	Limit Values		Unit
		min.	max.	
65	$\overline{\text{LRDY}}$ to LCLKO setup time		0	ns
66	$\overline{\text{LRDY}}$ to LCLKO hold time		25	ns

13.6.4 Local Bus Interface Arbitration Timing

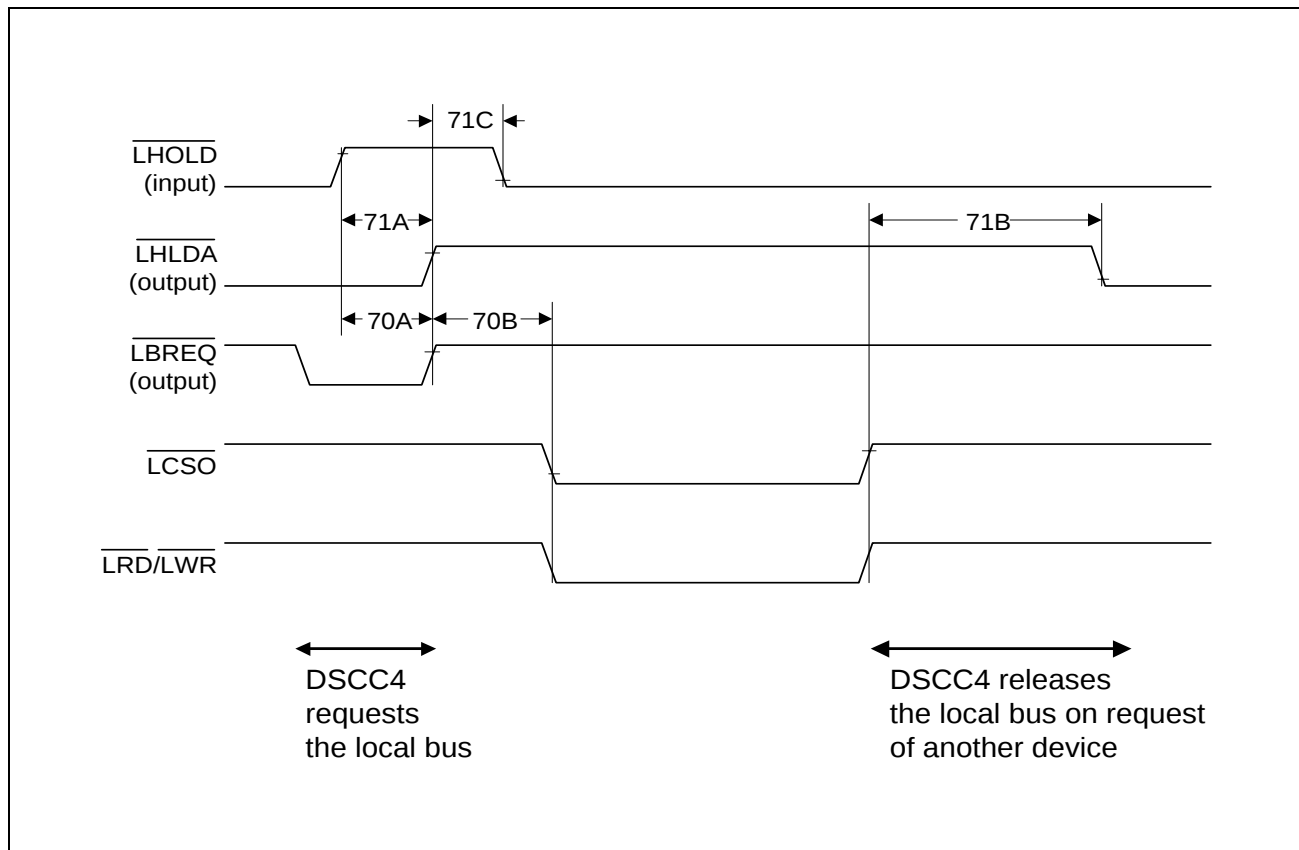


Figure 98 LBI Arbitration Timing

Table 124 LBI Arbitration Timing

No.	Parameter	Limit Values		Unit
		min.	max.	
70A	$\overline{\text{LHOLD}}$ inactive to $\overline{\text{LBREQ}}$ inactive delay	30		ns
70B	First master cycle start to $\overline{\text{LHOLDA}}$ inactive delay	120		ns
71A	$\overline{\text{LHOLD}}$ inactive to $\overline{\text{LHOLDA}}$ inactive delay	30		ns
71B	Last master cycle terminated to $\overline{\text{LHLDA}}$ active again	90		ns
71C	$\overline{\text{LBREQ}}$ active again to $\overline{\text{LHLDA}}$ inactive	60		ns

13.6.5 PCM Serial Interface Timing

13.6.5.1 Clock Input Timing

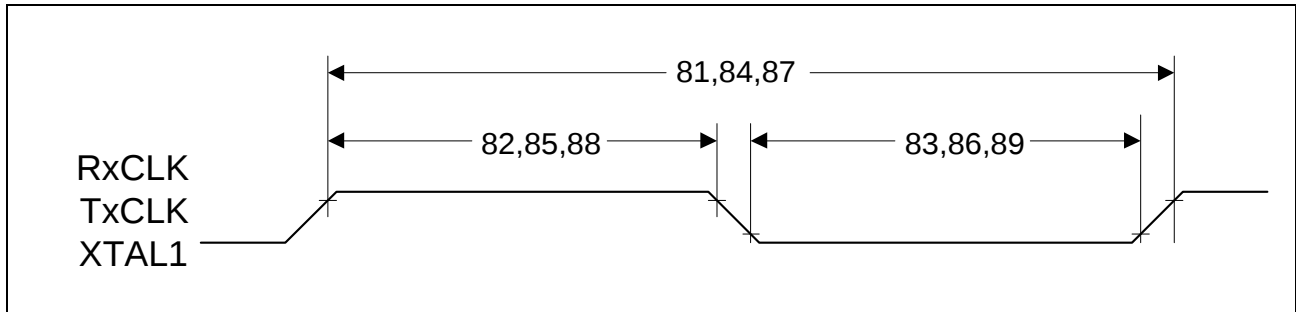


Figure 99 Clock Input Timing

Table 125 Clock Input Timing (non high speed modes)

No.	Parameter	Limit Values		Unit
		min.	max.	
81	RxCLK clock period	30		ns
82	RxCLK high time	13		ns
83	RxCLK low time	13		ns
84	TxCLK clock period	30		ns
85	TxCLK high time	13		ns
86	TxCLK low time	13		ns
87	XTAL1 clock period (internal oscillator used)	50		ns
	XTAL1 clock period (TTL clock signal supplied)	30		ns
88	XTAL1 high time (internal oscillator used)	23		ns
	XTAL1 high time (TTL clock signal supplied)	13		ns
89	XTAL1 low time (internal oscillator used)	23		ns
	XTAL1 low time (TTL clock signal supplied)	13		ns

Electrical Characteristics

Table 126 Clock Input Timing (high speed mode)

No.	Parameter	Limit Values		Unit
		min.	max.	
81	RxCLK clock period	19.2		ns
82	RxCLK high time	8.6		ns
83	RxCLK low time	8.6		ns
84	TxCLK clock period	19.2		ns
85	TxCLK high time	8.6		ns
86	TxCLK low time	8.6		ns

13.6.5.2 Receive Cycle Timing

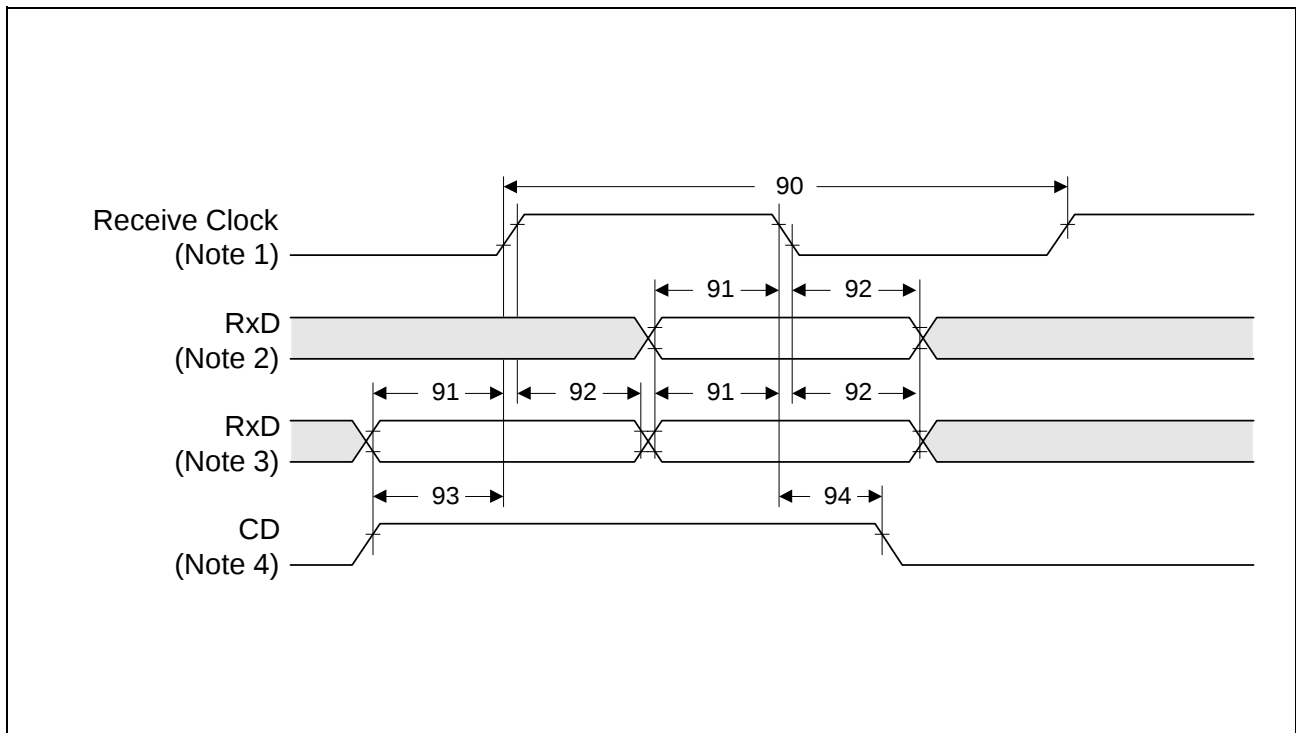


Figure 100 Receive Cycle Timing

Note:

1. Whichever supplies the receive clock depending on the selected clock mode:
externally clocked via RxCLK or XTAL1 or
internally clocked via DPLL, BRG or BCR.
(No edge relation can be measured if the internal receive clock is derived from the external clock source by division stages (BGR, BCR) or DPLL)
2. NRZ, NRZI and Manchester data encoding
3. FM0 and FM1 data encoding
4. If Carrier Detect auto start feature enabled (not for clock modes 1 and 5)
5. A receive clock must be present to detect input level changes of signal CD.

Electrical Characteristics

Table 127 Receive Cycle Timing

No.	Parameter		Limit Values		Unit
			min.	max.	
	Receive data rates	externally clocked (HDLC, high speed mode)		52	MBit/s
		externally clocked (non high speed)		10	MBit/s
		internally clocked (DPLL modes)		2	MBit/s
		internally clocked (non DPLL modes)		2	MBit/s
90	Clock period	externally clocked	19.2		ns
		internally clocked (DPLL modes)	480		ns
		internally clocked (non DPLL modes)	480		ns
91	RxD to RxCLK setup time		5		ns
92	RxD to RxCLK hold time		15		ns
93	CD to RxCLK rising edge setup time		10		ns
94	CD to RxCLK falling edge hold time		10		ns

13.6.5.3 Transmit Cycle Timing

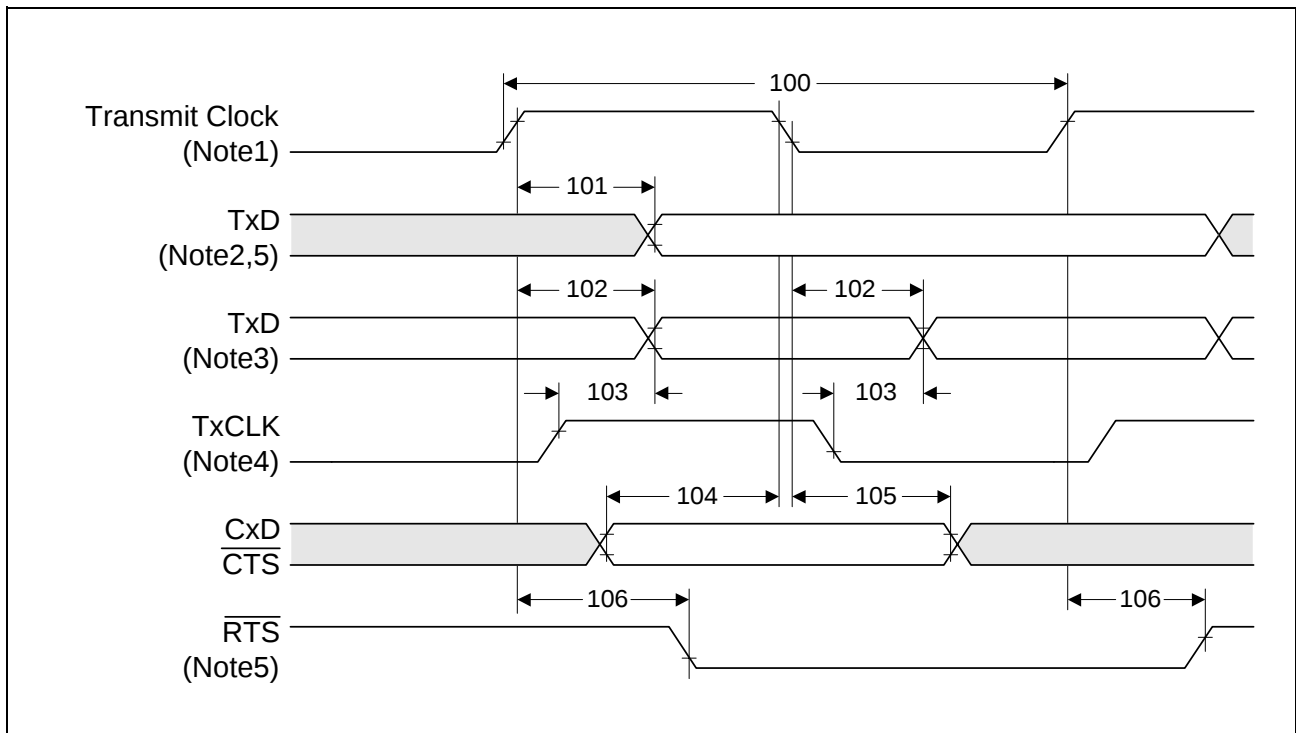


Figure 101 Transmit Cycle Timing

Note:

1. Whichever supplies the transmit clock depending on the selected clock mode:
externally clocked via TxCLK, RxCLK or XTAL1 or
internally clocked via DPLL, BRG or BCR.
(No edge relation can be measured if the internal transmit clock is derived from the external clock source by division stages (BGR, BCR) or DPLL)
2. NRZ, NRZI and Manchester data encoding
3. FM0 and FM1 data encoding
4. If TxCLK output feature is enabled (only in some clock modes)
5. The timing is valid for non bus configuration modes and bus configuration mode 1. In bus configuration mode 2, TxD and $\overline{\text{RTS}}$ are right shifted for 0.5 TxCLK periods i.e. driven by the falling TxCLK edge.
6. A transmit clock must be present to detect input level changes of signal $\overline{\text{CTS}}$ and to change the output level of signal $\overline{\text{RTS}}$.

Electrical Characteristics

Table 128 Transmit Cycle Timing

No.	Parameter		Limit Values		Unit
			min.	max.	
Transmit data rates		externally clocked (HDLC, high speed mode)		52	MBit/s
		externally clocked (non high speed)		10	MBit/s
		internally clocked (DPLL modes)		2	MBit/s
		internally clocked (non DPLL modes)		2	MBit/s
100	Clock period	externally clocked	19.2		ns
		internally clocked (DPLL modes)	480		ns
		internally clocked (non DPLL modes)	480		ns
101	TxD to TxCLK delay (NRZ, NRZI encoding)			35	ns
102	TxD to TxCLK delay (FM0, FM1, Manchester encoding)			35	ns
103	TxD to TxCLK(out) delay (if TxCLKO is enabled)		0	5	ns
104	CxD to TxCLK setup time, $\overline{\text{CTS}}$ to TxCLK setup time		10		ns
105	CxD to TxCLK hold time, $\overline{\text{CTS}}$ to TxCLK hold time		10		ns
106	$\overline{\text{RTS}}$ to TxCLK delay (not bus configuration mode)			35	ns
	$\overline{\text{RTS}}$ to TxCLK delay (bus configuration mode)			35	ns

13.6.5.4 Strobe Timing (clock mode 1)

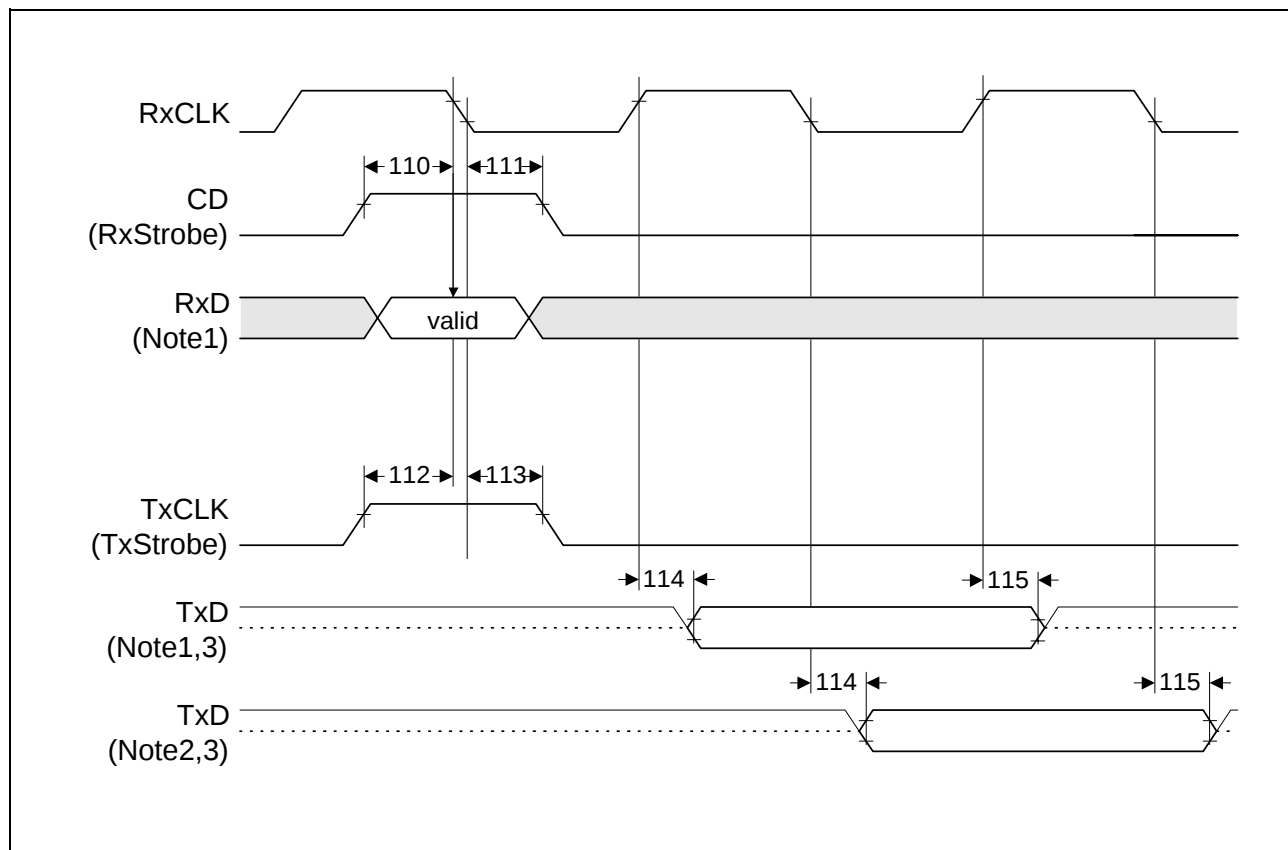


Figure 102 Strobe Timing

Note:

1. No bus configuration mode and bus configuration mode 1
2. Bus configuration mode 2
3. TxD Idle is either *active high* or *high impedance* if 'open drain' output type is selected.
4. A receive clock must be present to detect input level changes of signal CD.

Table 129 Strobe Timing (clock mode 1)

No.	Parameter	Limit Values		Unit
		min.	max.	
110	Receive strobe to RxCLK setup	5		ns
111	Receive strobe to RxCLK hold	15		ns
112	Transmit strobe to RxCLK setup	5		ns
113	Transmit strobe to RxCLK hold	15		ns

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Table 129 Strobe Timing (clock mode 1)

No.	Parameter	Limit Values		Unit
		min.	max.	
114	TxD to RxCLK delay	35		ns
115	TxD to RxCLK high impedance delay	35		ns

13.6.5.5 Frame Synchronisation Timing (clock mode 5)

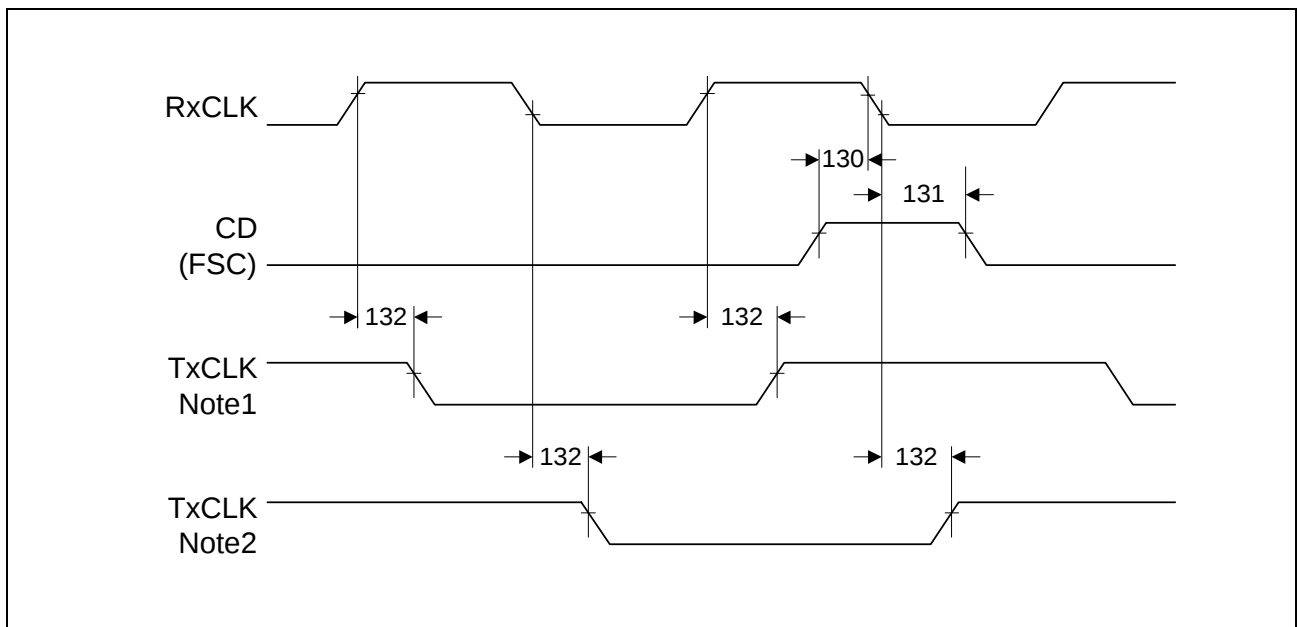


Figure 103 Frame Synchronisation Timing

Note:

1. No bus configuration mode and bus configuration mode 1
2. Bus configuration mode 2

Table 130 Frame Synchronisation Timing (clock mode 5)

No.	Parameter	Limit Values		Unit
		min.	max.	
130	Sync pulse to RxCLK setup time	5		ns
131	Sync pulse to RxCLK hold time	5		ns
132	TxCLKout to RxCLK delay (time slot monitor)	10	40	ns

13.6.5.6 High Speed Receive Cycle Timing

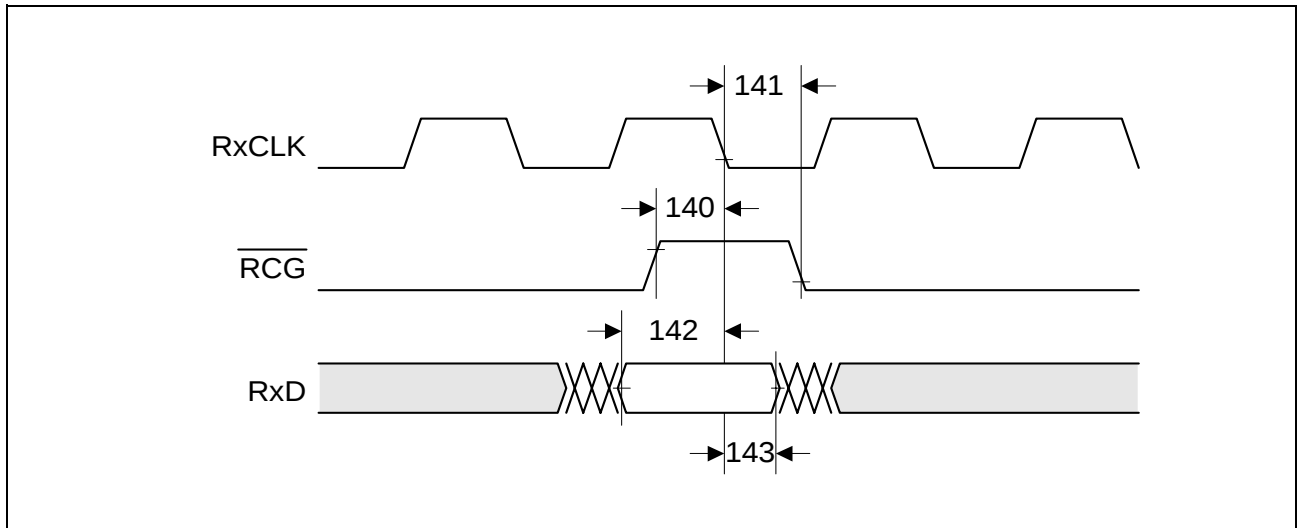


Figure 104 High Speed Receive Timing

Table 131 High Speed Receive Timing

No.	Parameter	Limit Values		Unit
		min.	max.	
140	$\overline{\text{RCG}}$ setup time	5		ns
141	$\overline{\text{RCG}}$ hold time	5		ns
142	RxD setup time	5		ns
143	RxD hold time	5		ns

13.6.5.7 High Speed Transmit Cycle Timing

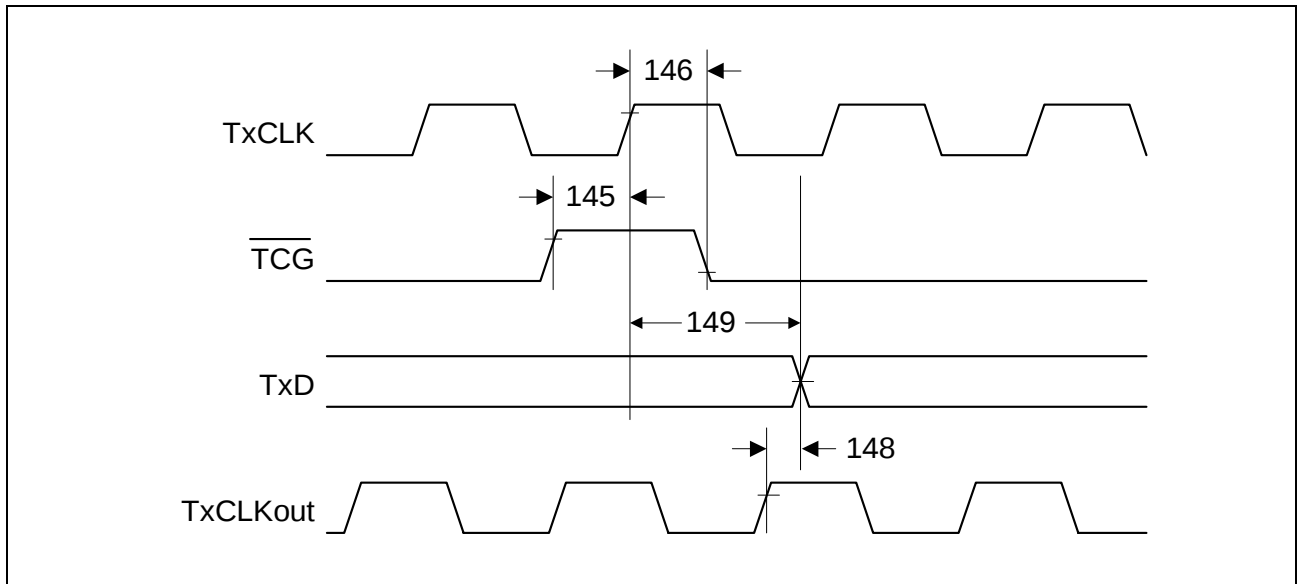


Figure 105 High Speed Transmit Timing

Table 132 High Speed Transmit Timing

No.	Parameter	Limit Values		Unit
		min.	max.	
145	TCG setup time	5		ns
146	TCG hold time	5		ns
148	TxCLKout to TxD delay	0	5	ns
149	TxCLK to TxD delay	5	16.5	ns

13.6.6 Reset Timing

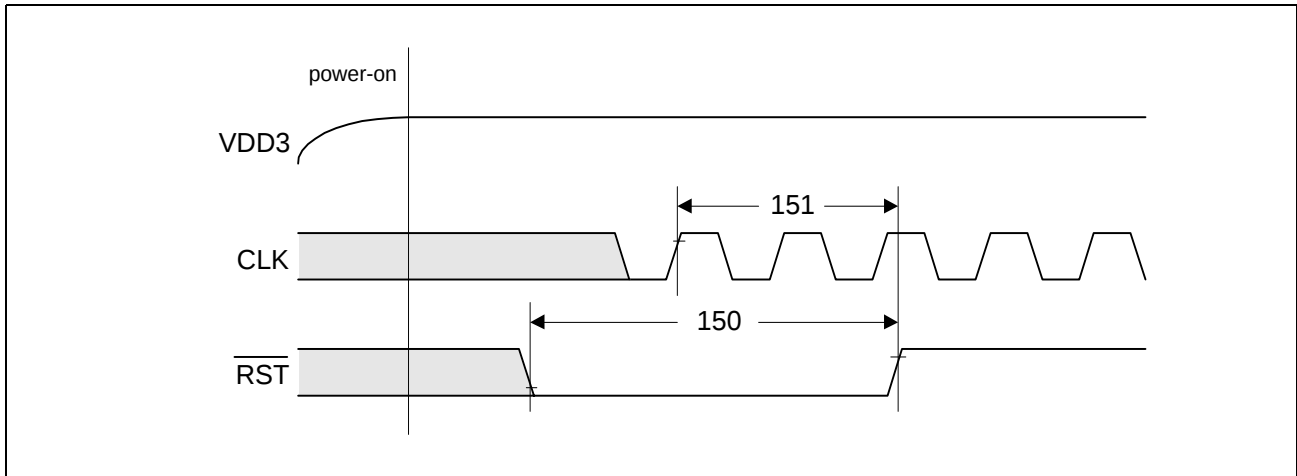


Figure 106 Reset Timing

Table 133 Reset Timing

No.	Parameter	Limit Values		Unit
		min.	max.	
150	RESET pulse width	120		ns
150	Number of CLK cycles during $\overline{RST}$ active	2		CLK cycles

Note: $\overline{RST}$ may be asynchronous to CLK when asserted or deasserted. RST may be asserted during power-up or asserted after power-up. Nevertheless deassertion must be clean, bounce-free edge as recommended by PCI Spec. Revision 2.1.

Note: $\overline{RST}$ signal timing is independent of whether PCI or De-multiplexed mode is selected via pin DEMUX.

13.6.7 JTAG-Boundary Scan Timing

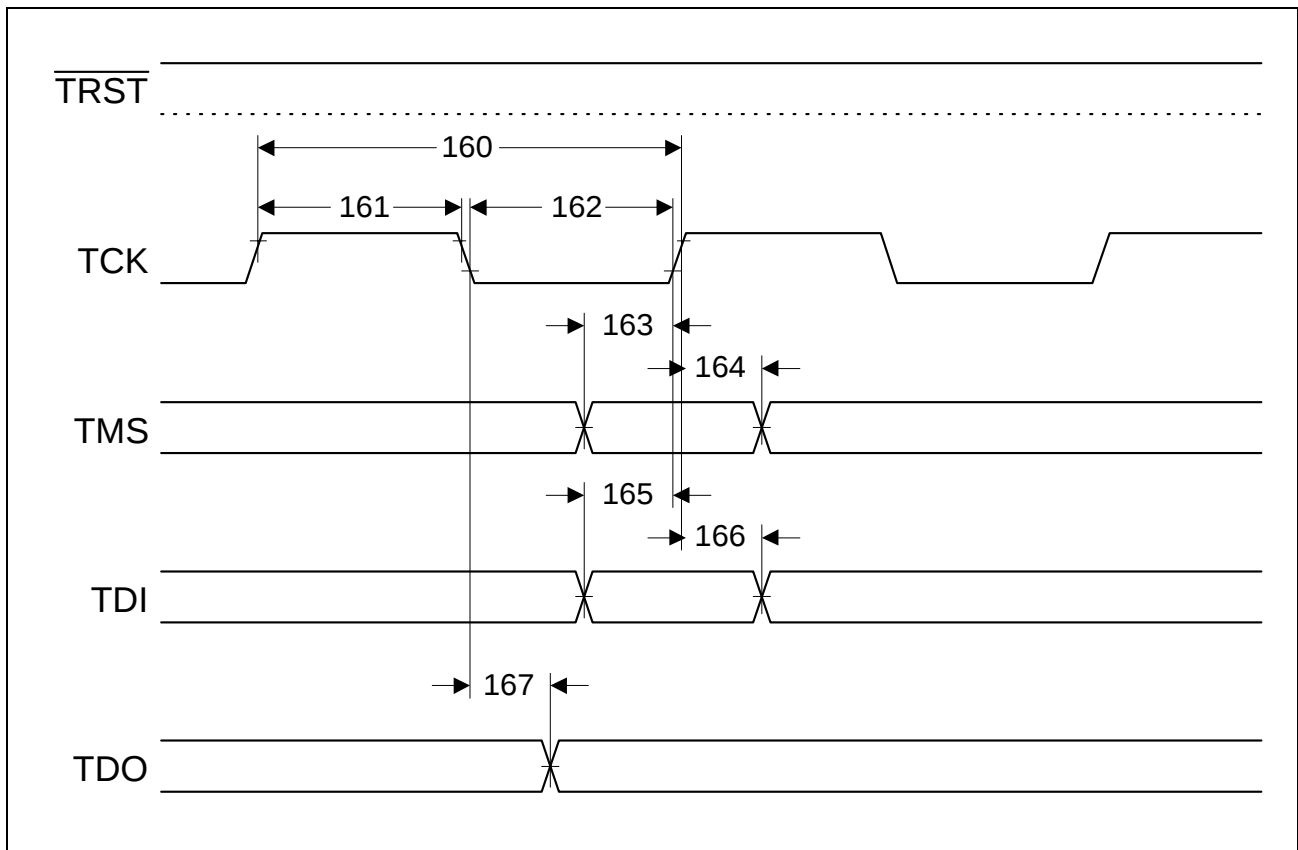


Figure 107 JTAG-Boundary Scan Timing

Table 134 JTAG-Boundary Scan Timing

No.	Parameter	Limit Values		Unit
		min.	max.	
160	TCK period	166	∞	ns
161	TCK high time	80		ns
162	TCK low time	80		ns
163	TMS setup time	30		ns
164	TMS hold time	10		ns
165	TDI setup time	30		ns
166	TDI hold time	20		ns
167	TDO valid delay	60		ns

13.6.8 SSC Serial Interface Timing

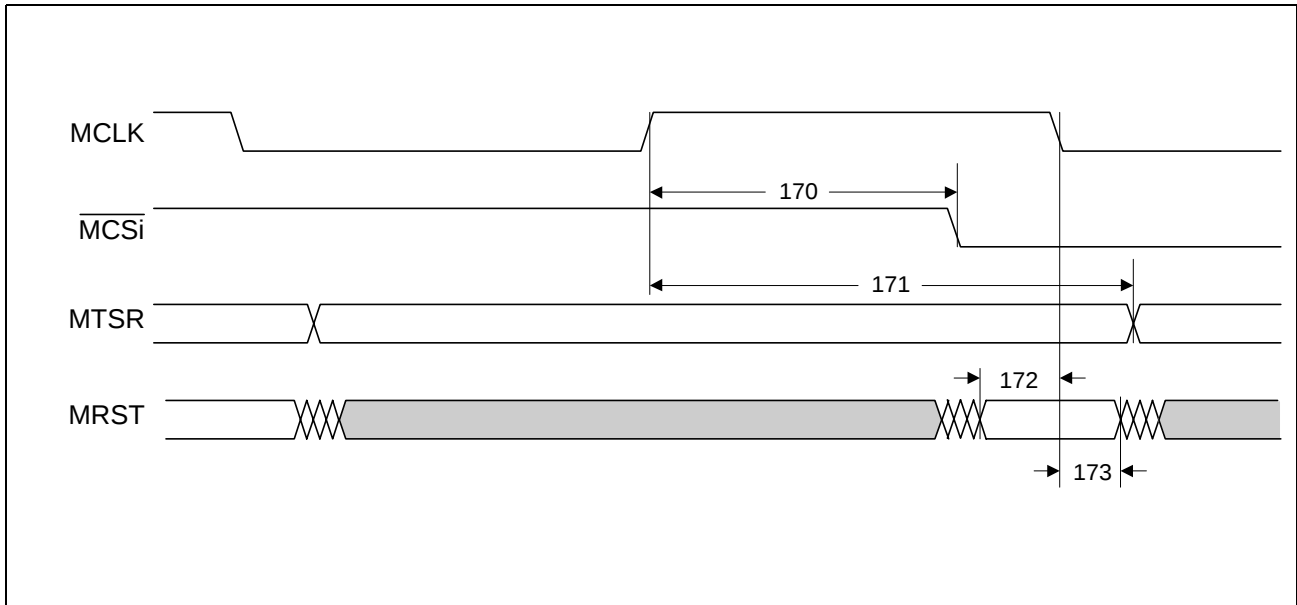


Figure 108 SSC Interface Timing (Master)

Table 135 SSC Interface Timing

No.	Parameter	Limit Values		Unit
		min.	max.	
170	MCLK high to $\overline{\text{MCSi}}$ active delay		$2T_{\text{CLK}} + 40$	ns
171	MCLK high to MTSR delay (Master)		$2T_{\text{CLK}} + 40$	ns
	MCLK high to MRST delay (Slave) ¹⁾		$4T_{\text{CLK}} + 40$	ns
172	MRST setup time	$T_{\text{CLK}} + 20$		ns
173	MRST hold time	$T_{\text{CLK}} + 20$		ns

¹⁾ In SSC 'Slave Mode', signal MRST is output and MTSR is input.

Note: T_{CLK} is the CLK signal time period.

14 Package Outlines

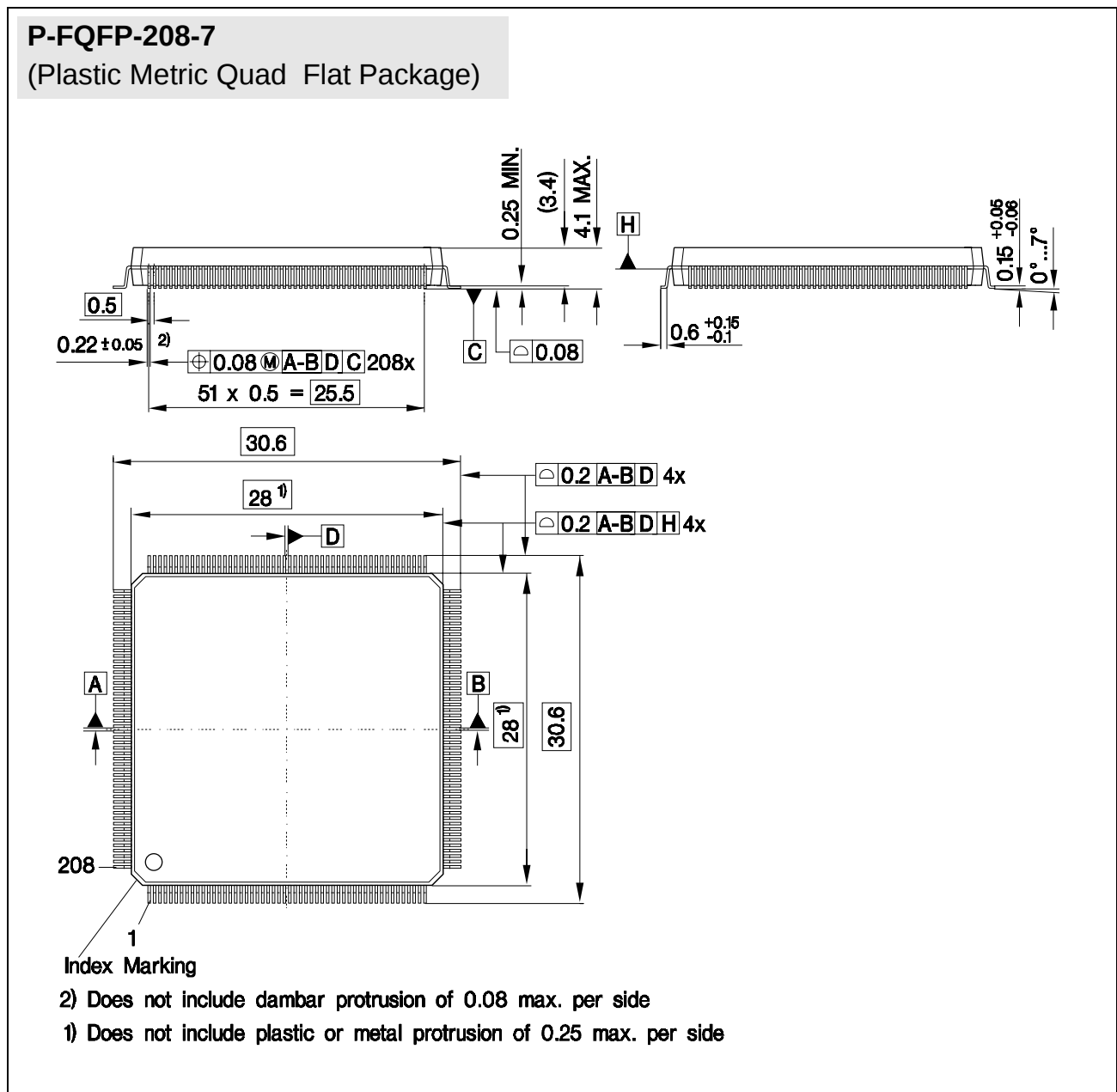


Figure 109 Package Outline

Sorts of Packing

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

SMD = Surface Mounted Device

Dimensions in mm